

Service
Service
Service



Service Manual

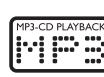


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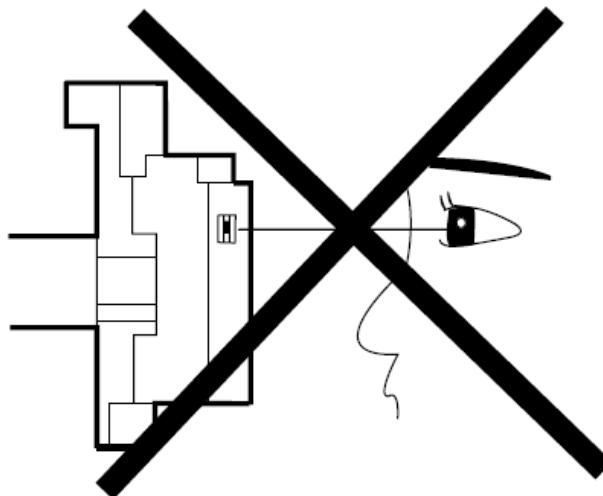
Version 1.0



PHILIPS

LASER BEAM SAFETY PRECAUTIONS

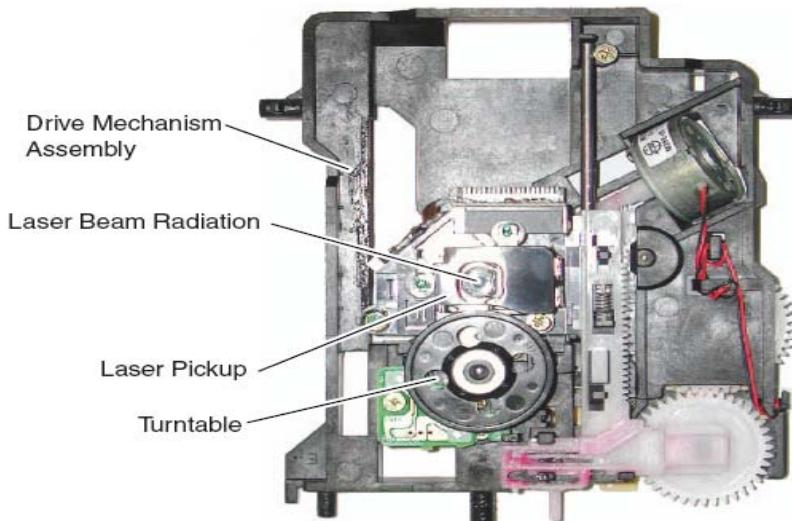
This DVD player uses a pickup that emits a laser beam.



Do not look directly at the laser beam coming from the pickup or allow it to strike against your skin.

The laser beam is emitted from the location shown in the figure. When checking the laser diode, be sure to keep your eyes at least 30 cm away from the pickup lens when the diode is turned on. Do not look directly at the laser beam.

CAUTION: Use of controls and adjustments, or doing procedures other than those specified herein, may result in hazardous radiation exposure.



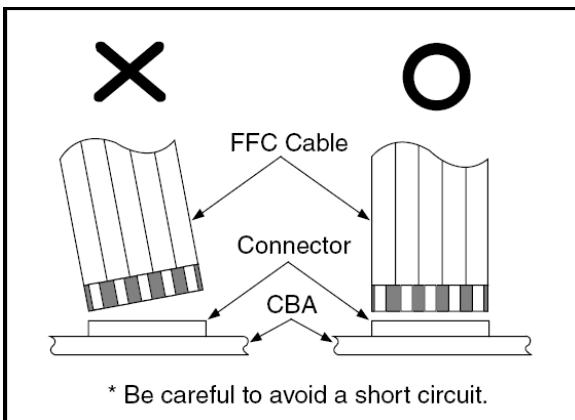
CAUTION
LASER RADIATION
WHEN OPEN. DO NOT
STARE INTO BEAM.

Location: Top of DVD mechanism.

STANDARD NOTES FOR SERVICING

Instructions for Connectors

1. When you connect or disconnect the FFC (Flexible Foil Connector) cable, be sure to first disconnect the AC cord.
2. FFC (Flexible Foil Connector) cable should be inserted parallel into the connector, not at an angle.



Pb (Lead) Free Solder

When soldering, be sure to use the Pb free solder.



IDENTIFICATION:

Regardless of special logo (not always indicated)

One must treat all sets from 1.1.2005 onwards, according next rules.

Important note: In fact also products a little older can also be treated in this way as long as you avoid mixing solder-alloys (leaded/lead-free). So best to always use SAC305 and the higher temperatures belong to this.

Due to lead-free technology some rules have to be respected by the workshop during a repair:

■ Use only lead-free solder alloy Philips SAC305 with order code 0622 149 00106. If lead-free solder paste is required, please contact the manufacturer of your solder-equipment. In general use of solder paste within workshops should be avoided because paste is not easy to store and to handle.

- Use only adequate solder tools applicable for leadfree solder alloy. The solder tool must be able
 - To reach at least a solder-temperature of 400°C,
 - To stabilize the adjusted temperature at the solder-tip
 - To exchange solder-tips for different applications.
- Adjust your solder tool so that a temperature around 360°C - 380°C is reached and stabilized at the solder joint. Heating-time of the solder-joint should not exceed ~ 4 sec. Avoid temperatures above 400°C otherwise wear-out of tips will rise drastically and flux-fluid will be destroyed. To avoid wear-out of tips switch off un-used equipment, or reduce heat.
- Mix of lead-free solder alloy / parts with leaded solder alloy / parts is possible but PHILIPS recommends strongly to avoid mixed solder alloy types (leaded and lead-free). If one cannot avoid, clean carefully the solder-joint from old solder alloy and re-solder with new solder alloy (SAC305).
- Use only original spare-parts listed in the Service-Manuals. Not listed standard-material (commodities) has to be purchased at external companies.
- Special information for BGA-ICs:
 - always use the 12nc-recognizable soldering temperature profile of the specific BGA (for desoldering always use highest lead-free

temperature profile, in case of doubt)
 - lead free BGA-ICs will be delivered in so-called 'dry-packaging' (sealed pack including a silica gel pack) to protect the IC against moisture. After opening, dependent of MSL-level seen on indicatorlabel in the bag, the BGA-IC possibly still has to be baked dry. This will be communicated via AYS-website.

Do not re-use BGAs at all.

- For sets produced before 1.1.2005, containing leaded soldering-tin and components, all needed spare-parts will be available till the end of the service-period. For repair of such sets nothing changes.

- On our website

www.atyourservice.ce.Philips.com you find more information to:

- BGA-de-/soldering (+ baking instructions)
- Heating-profiles of BGAs and other ICs used in Philips-sets.

You will find this and more technical information within the "magazine", chapter "workshop news".

For additional questions please contact your local repair-helpdesk.

How to Remove / Install Flat Pack-IC

1. Removal

With Hot-Air Flat Pack-IC Desoldering Machine:

1. Prepare the hot-air flat pack-IC desoldering machine, then apply hot air to the Flat Pack-IC (about 5 to 6 seconds). (Fig. S-1-1)

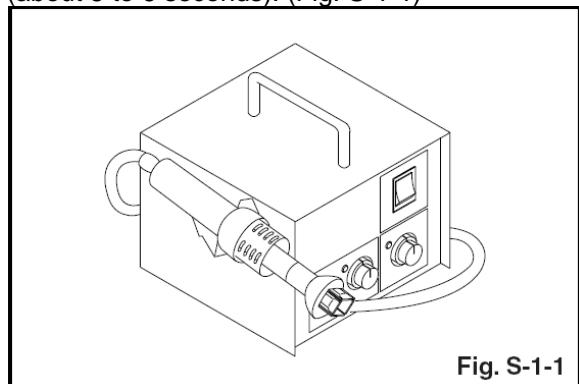


Fig. S-1-1

2. Remove the flat pack-IC with tweezers while applying the hot air.

3. Bottom of the flat pack-IC is fixed with glue to the CBA; when removing entire flat pack-IC, first apply soldering iron to center of the flat pack-IC and heat up. Then remove (glue will

be melted). (Fig. S-1-6)

4. Release the flat pack-IC from the CBA using tweezers. (Fig. S-1-6)

CAUTION:

1. The Flat Pack-IC shape may differ by models. Use an appropriate hot-air flat pack-IC desoldering machine, whose shape matches that of the Flat Pack-IC.
2. Do not supply hot air to the chip parts around the flat pack-IC for over 6 seconds because damage to the chip parts may occur. Put masking tape around the flat pack-IC to protect other parts from damage. (Fig. S-1-2)
3. The flat pack-IC on the CBA is affixed with glue, so be careful not to break or damage the foil of each pin or the solder lands under the IC when removing it.

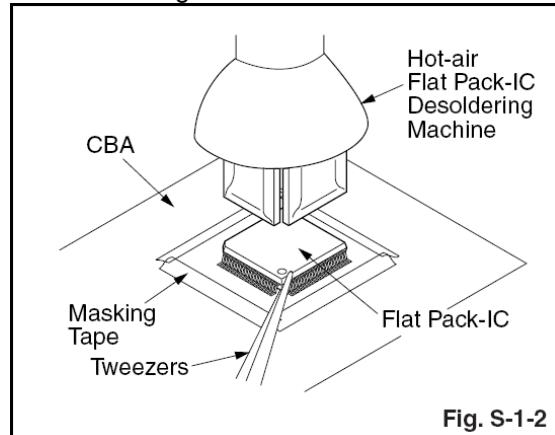


Fig. S-1-2

With Soldering Iron:

1. Using desoldering braid, remove the solder from all pins of the flat pack-IC. When you use solder flux which is applied to all pins of the flat pack-IC, you can remove it easily. (Fig. S-1-3)

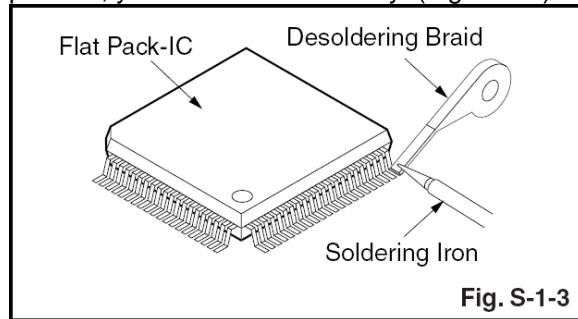


Fig. S-1-3

2. Lift each lead of the flat pack-IC upward one by one, using a sharp pin or wire to which solder will not adhere (iron wire). When heating the pins, use a fine tip soldering iron or a hot air desoldering machine. (Fig. S-1-4)

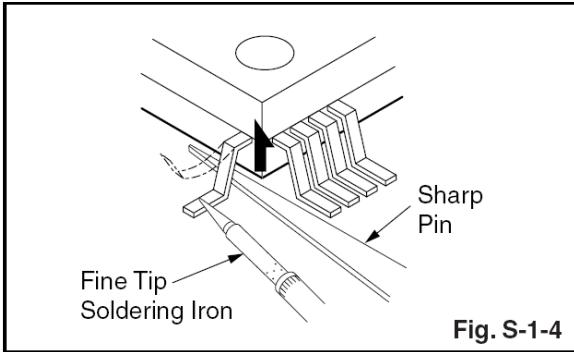


Fig. S-1-4

3. Bottom of the flat pack-IC is fixed with glue to the CBA; when removing entire flat pack-IC, first apply soldering iron to center of the flat pack-IC and heat up. Then remove (glue will be melted). (Fig. S-1-6)
4. Release the flat pack-IC from the CBA using tweezers. (Fig. S-1-6)

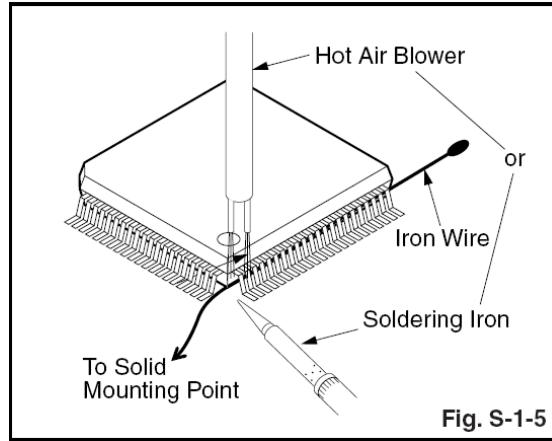


Fig. S-1-5

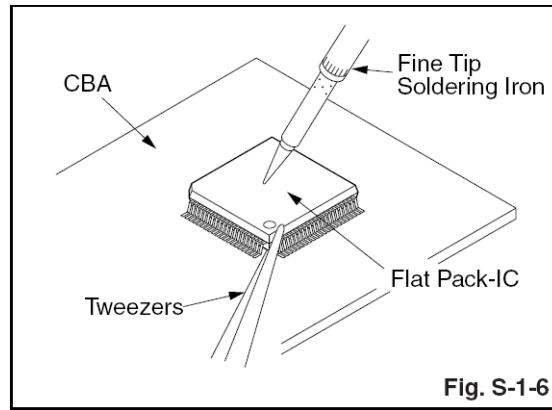


Fig. S-1-6

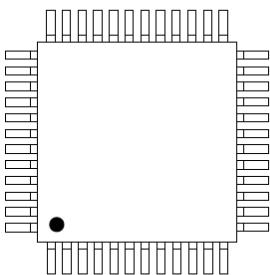
With Iron Wire:

1. Using desoldering braid, remove the solder from all pins of the flat pack-IC. When you use solder flux which is applied to all pins of the flat pack-IC, you can remove it easily. (Fig. S-1-3)
 2. Affix the wire to a workbench or solid mounting point, as shown in Fig. S-1-5.
 3. While heating the pins using a fine tip soldering iron or hot air blower, pull up the wire as the solder melts so as to lift the IC leads from the CBA contact pads as shown in Fig. S-1-5.
 4. Bottom of the flat pack-IC is fixed with glue to the CBA; when removing entire flat pack-IC, first apply soldering iron to center of the flat pack-IC and heat up. Then remove (glue will be melted). (Fig. S-1-6)
 5. Release the flat pack-IC from the CBA using tweezers. (Fig. S-1-6)
- Note:** When using a soldering iron, care must be taken to ensure that the flat pack-IC is not being held by glue. When the flat pack-IC is removed from the CBA, handle it gently because it may be damaged if force is applied.

2. Installation

1. Using desoldering braid, remove the solder from the foil of each pin of the flat pack-IC on the CBA so you can install a replacement flat pack-IC more easily.
2. The “●” mark on the flat pack-IC indicates pin 1. (See Fig. S-1-7.) Be sure this mark matches the 1 on the PCB when positioning for installation. Then presolder the four corners of the flat pack-IC. (See Fig. S-1-8.)
3. Solder all pins of the flat pack-IC. Be sure that none of the pins have solder bridges.

Example :



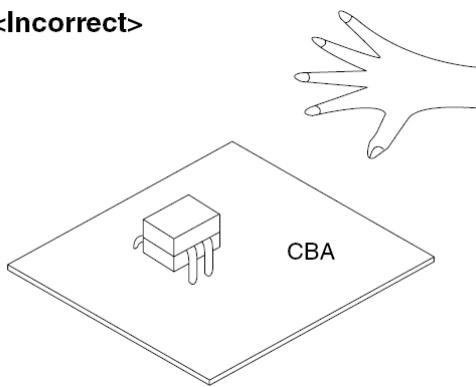
Pin 1 of the Flat Pack-IC
is indicated by a "●" mark.

Fig. S-1-7

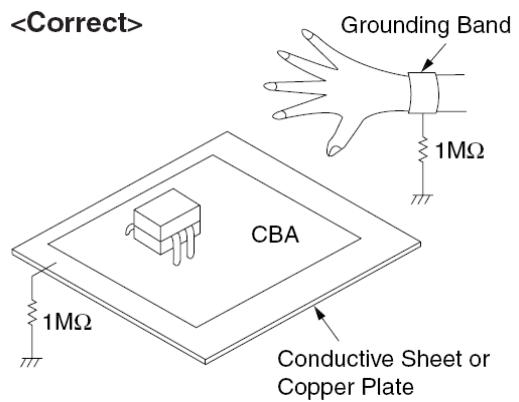
2. Ground for Workbench

Be sure to place a conductive sheet or copper plate with proper grounding ($1 M\Omega$) on the workbench or other surface, where the semi-conductors are to be placed. Because the static electricity charge on clothing will not escape through the body grounding band, be careful to avoid contacting semi-conductors with your clothing.

<Incorrect>



<Correct>



Instructions for Handling

Semiconductors

Electrostatic breakdown of the semi-conductors may occur due to a potential difference caused by electrostatic charge during unpacking or repair work.

1. Ground for Human Body

Be sure to wear a grounding band ($1 M\Omega$) that is properly grounded to remove any static electricity that may be charged on the body.

Safety and important notice



Warning

- Risk of overheating! Never install the Home Theater System in a confined space. Always leave a space of at least 4 inches around the Home Theater System for ventilation. Ensure curtains or other objects never cover the ventilation slots on the Home Theater System.
- Never place the Home Theater System, remote control or batteries near naked flames or other heat sources, including direct sunlight.
- Only use this Home Theater System indoors. Keep this Home Theater System away from water, moisture and liquid-filled objects.
- Never place this Home Theater System on other electrical equipment.
- Keep away from this Home Theater System during lightning storms.
- Where the mains plug or an appliance coupler is used as the disconnect device, the disconnect device shall remain readily operable.
- Visible and invisible laser radiation when open
Avoid exposure to beam.

Copyright notice



Be responsible Respect copyrights

This product incorporates copyright protection technology that is protected by method claims of certain U.S. patents and other intellectual property rights owned by Macrovision Corporation and other rights owners. Use of this copyright protection technology must be authorised by Macrovision Corporation, and is intended for home and other limited viewing uses only unless otherwise authorised by Macrovision Corporation. Reverse engineering or disassembly is prohibited.

About Progressive Scan

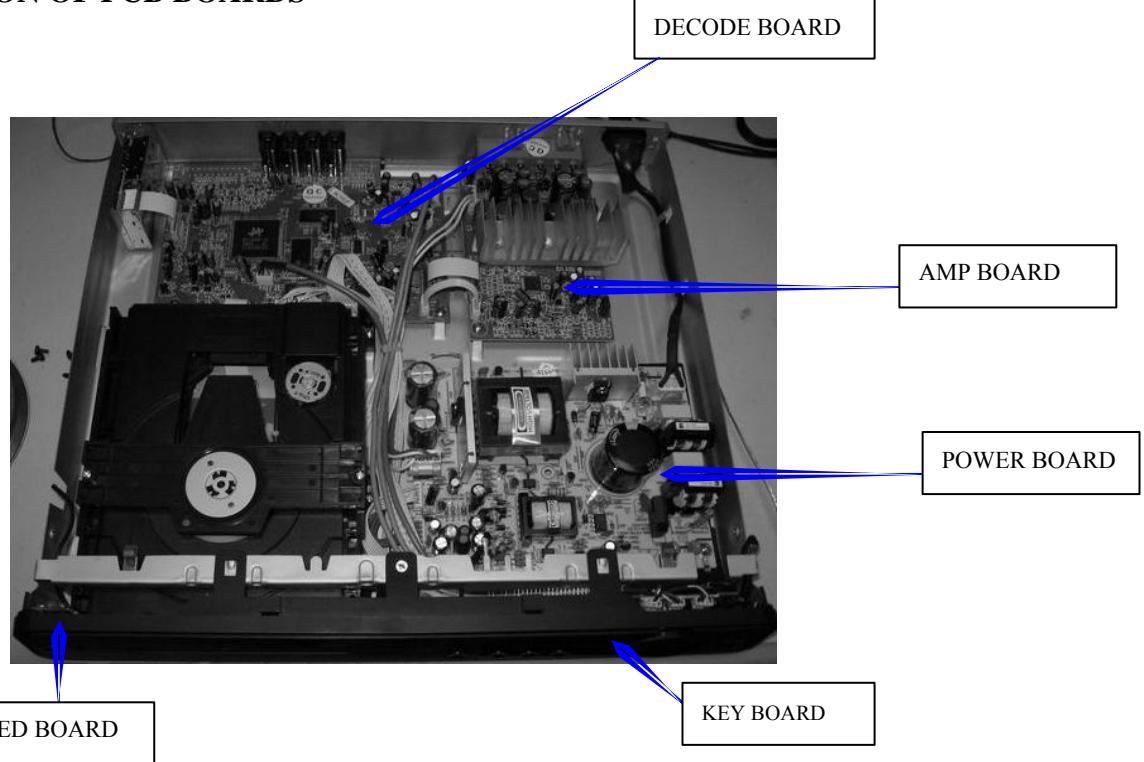
Consumers should note that not all high definition television sets are fully compatible with this product and may cause artifacts to be displayed in the picture. In case of 525 or 625 progressive scan picture problems, it is recommended that the user switch the connection to the 'standard definition' output. If there are questions regarding our TV set compatibility with this model 525p and 625p DVD player, please contact our customer service center.

Recycle notice



This electronic equipment contains a large number of materials that can be recycled or reused if disassembled by a specialized company. If you are disposing of an old machine, please take it to a recycling center. Please observe the local regulations regarding disposal of packaging materials, exhausted batteries and old equipment.

LOCATION OF PCB BOARDS



VERSION VARIATION:

Type/Versions	HTS3181	HTS3181X
Features	/55	/78
Output Power-300W	X	X
Voltage(110V-240V)	X	X

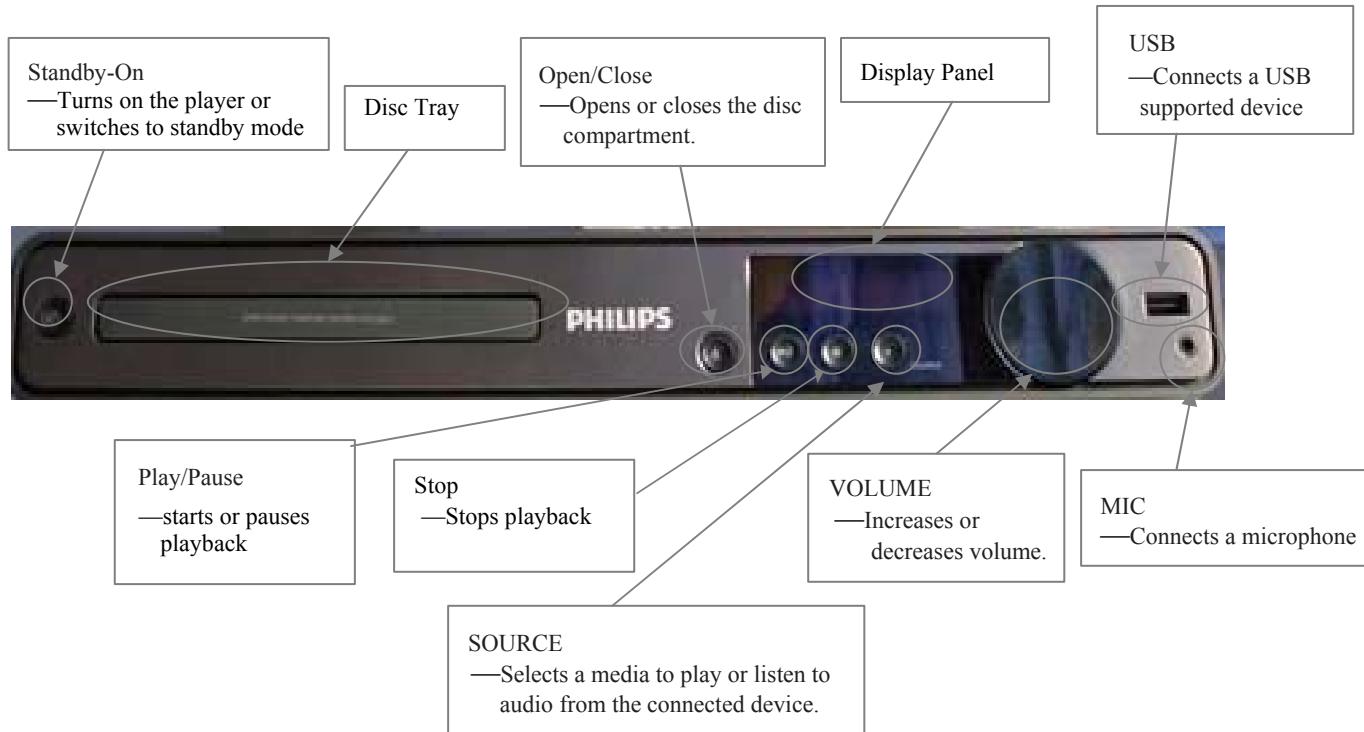
SERVICE SCENARIO MATRIX:

Type/Versions	HTS3181	HTS3181X
Board in used	/55	/78
DECODE board	C	C
POWER board	C	C
AMP board	C	C
LED board	C	C
KEY board	C	C

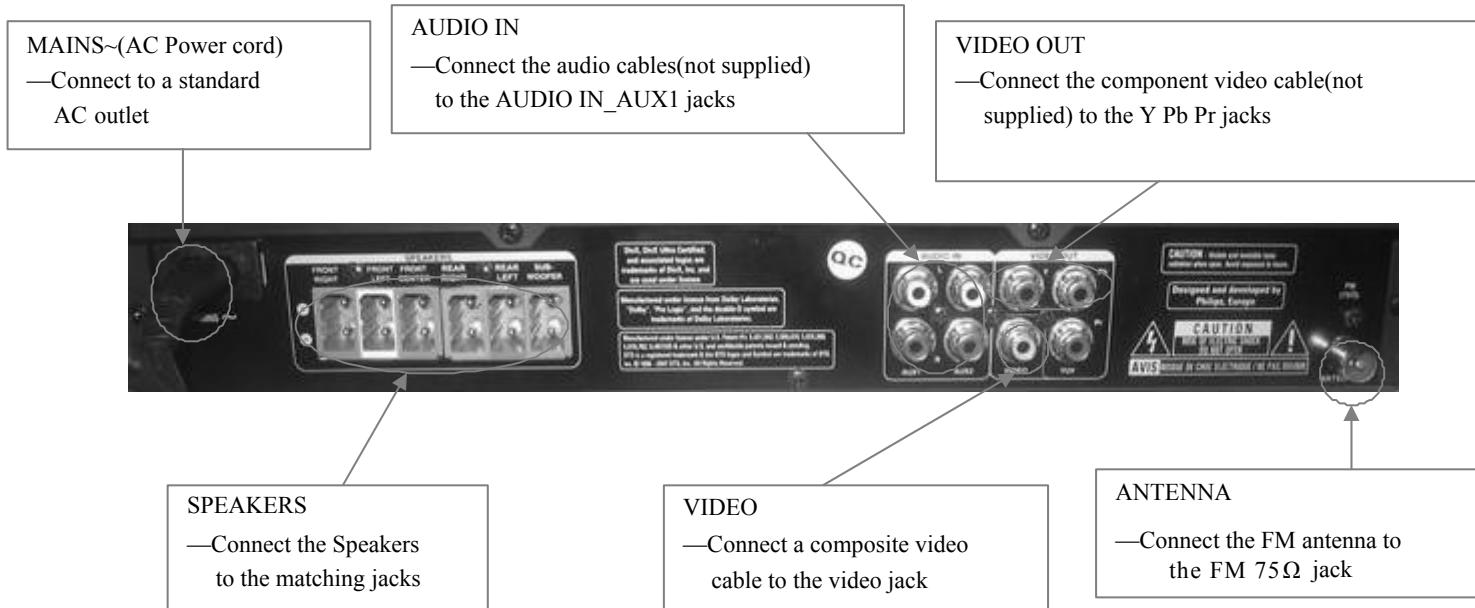
*C=Component Level Repair

OPERATING CONTROLS AND FUNCTIONS

Front Panel

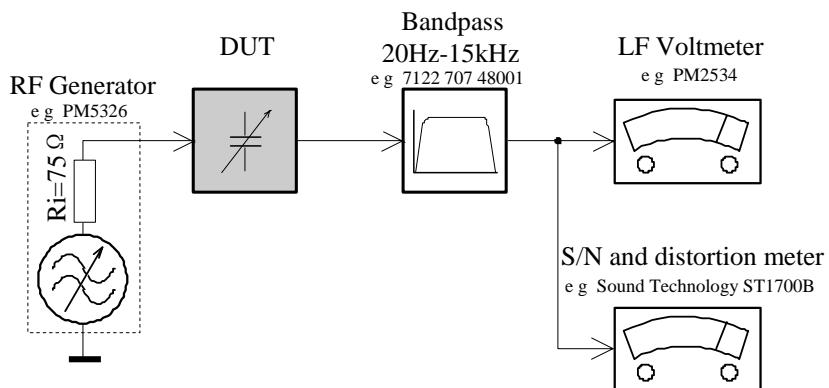


Back Panel



MEASUREMENT SETUP

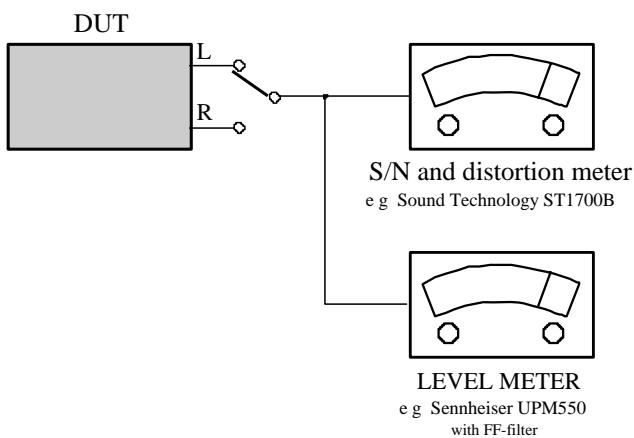
Tuner FM



Use a bandpass filter to eliminate hum (50Hz, 100Hz) and disturbance from the pilottone (19kHz, 38kHz).

CD

Use Audio Signal Disc SBC429 4822 397 30184
(replaces test disc 3)



System , Region Code , etc. Setting Procedure

1) System Reset

- a) Press "SETUP" button on RC, TV will show setup menu
- b) Select the menu using the ▼ and ► on RC
- c) Go preference page to do system reset

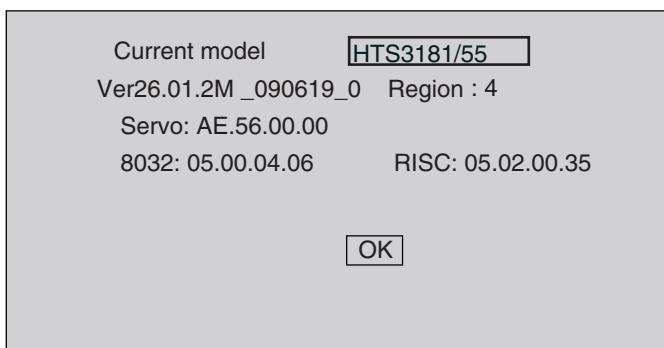
2) Region Code Change

- a) In open model, press "9" "9" "9" "9" on R/C, then input desired number to change region code :

1	USA
2	EU
3	AP
4	Australia , NZ , Latam
5	Russia , INDIA
6	CHINA

3) Version Control Change

- a) In open model, press "1" "5" "9" on RC
- b) Press ► and select version you want using ▼
- c) Press ► and "ok" button to confirm
- d) TV will show message as below:



4) Password Change

- a) Press "SETUP" button on R/C, TV will show setup menu
- b) Select the menu using the ▼ and ► on RC
- c) Go preference page select "password" to change
* 136900 is default password supplied.

5) Check on the Software Version

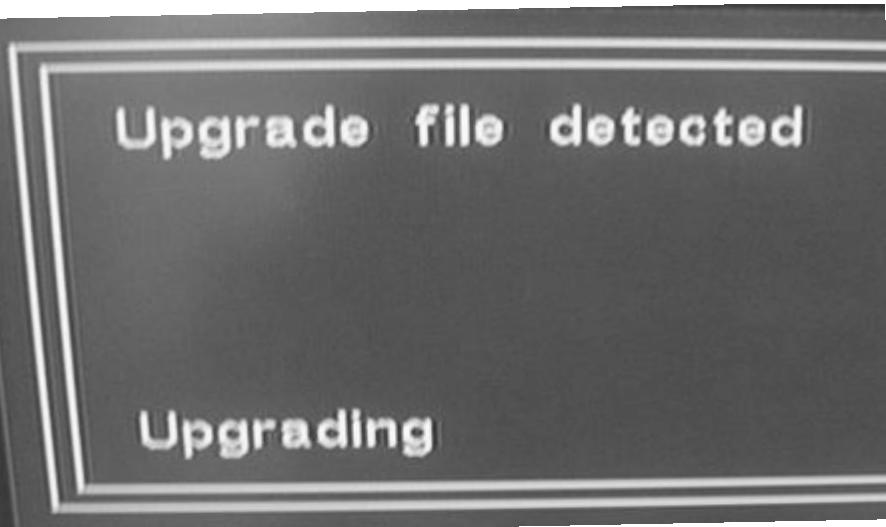
- a) Press "SETUP" button on R/C, TV will show setup menu
- b) Select the menu using the ▼ and ► on RC
- c) Go preference page select "Version Info".
TV will show the version on screen.

6) Trade mode

- a) Press "Open/Close" button on RC
- b) Press "2" "5" "9" on R/C, VFD will display "TRA ON" or "TRA OFF"

7) Upgrading new software

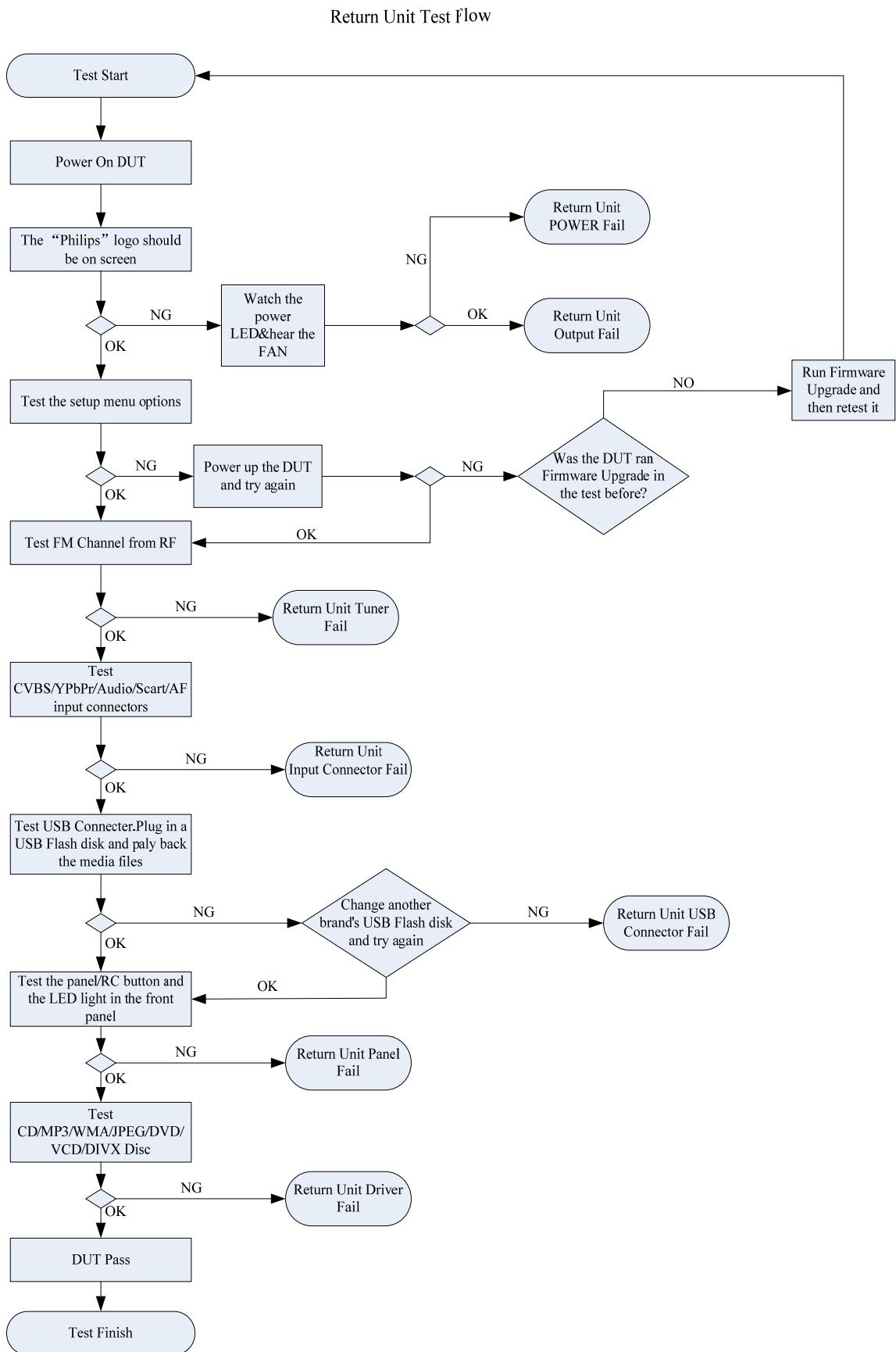
- a) Copy "software files" into a CD-R or USB flash drive.
- b) Insert the CD-R disc or USB flash drive.
- c) Press DISC or USB, the system will identify the update file automatically.
- d) VFD will show "Updating" until update is complete.
* the system will switch off to standby automatically after update is complete.
- e) OSD will show:

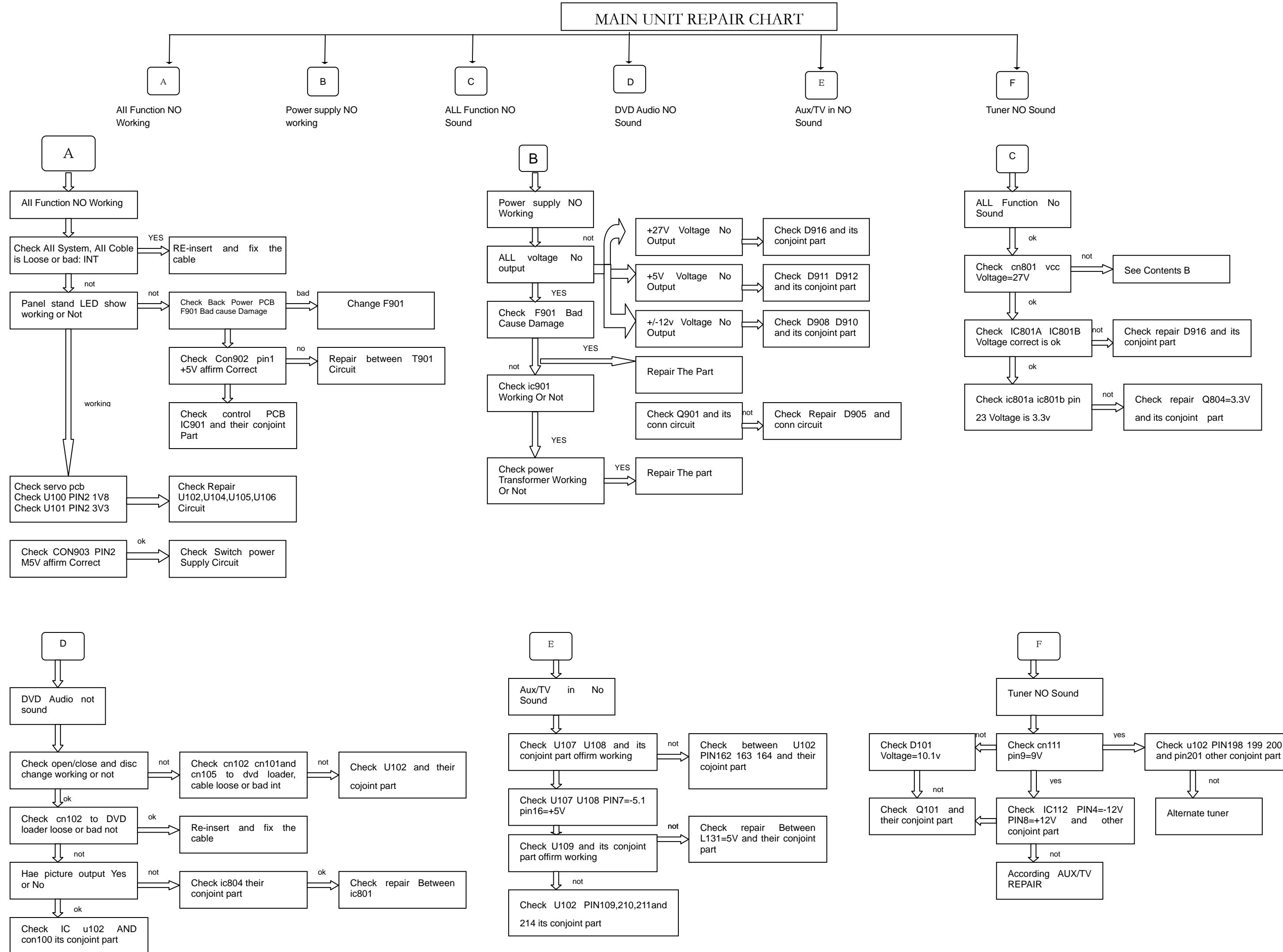


CAUTION!

This information is confidential and may not be distributed. Only a qualified service person should reprogram the Region Code.

Flow chart on how to filter between working &defective sets

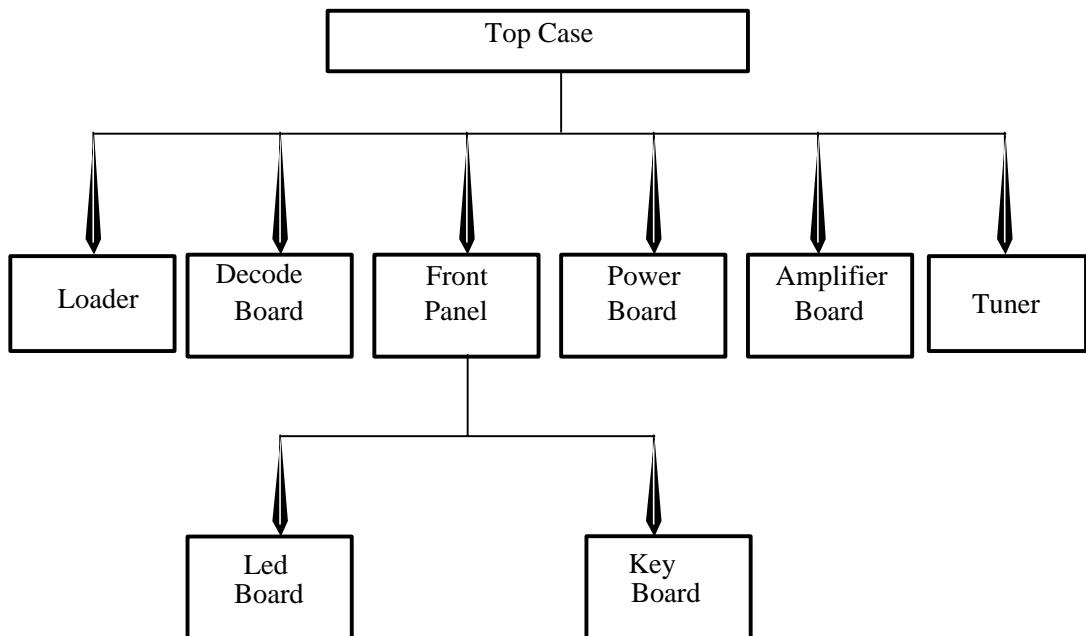




DISASSEMBLY INSTRUCTIONS

1. Disassembly Flowchart

This flowchart indicates the disassembly steps to gain access to item(s) to be serviced. When reassembling, follow the steps in reverse order. Bend, route, and dress the cables as they were originally.



2. Dismantling of top case

2-1. Ensure no disc in the tray and keep tray close, turn off the DVD player and then disconnect the mains supply.

Loosen 6 screws“A” as shown in figure 2-1.

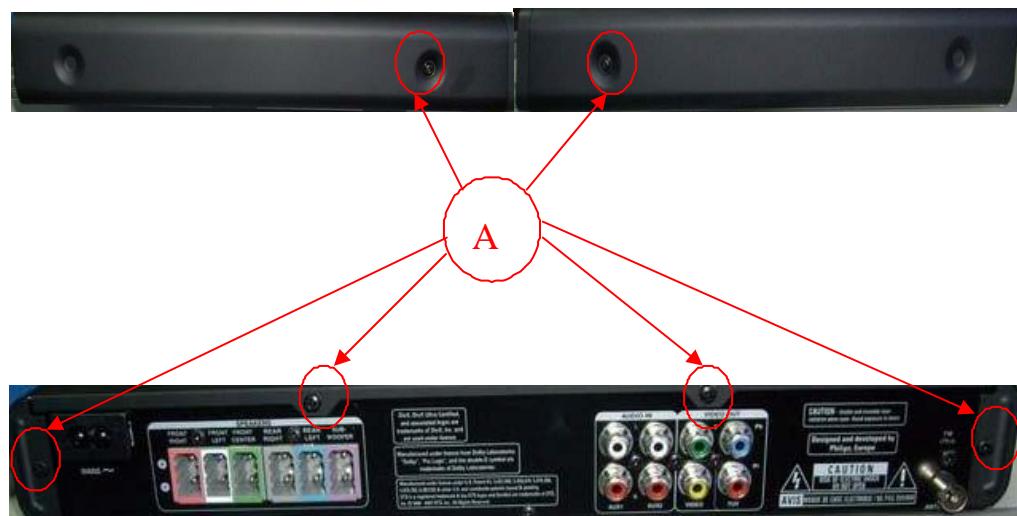


Figure 2-1.

2-2. Take off the top case as shown in figure 2-2.



Figure 2-2.

3. Dismantling of led+key board

3-1. Loosen 4 screws “B” as shown in figure 3-1.

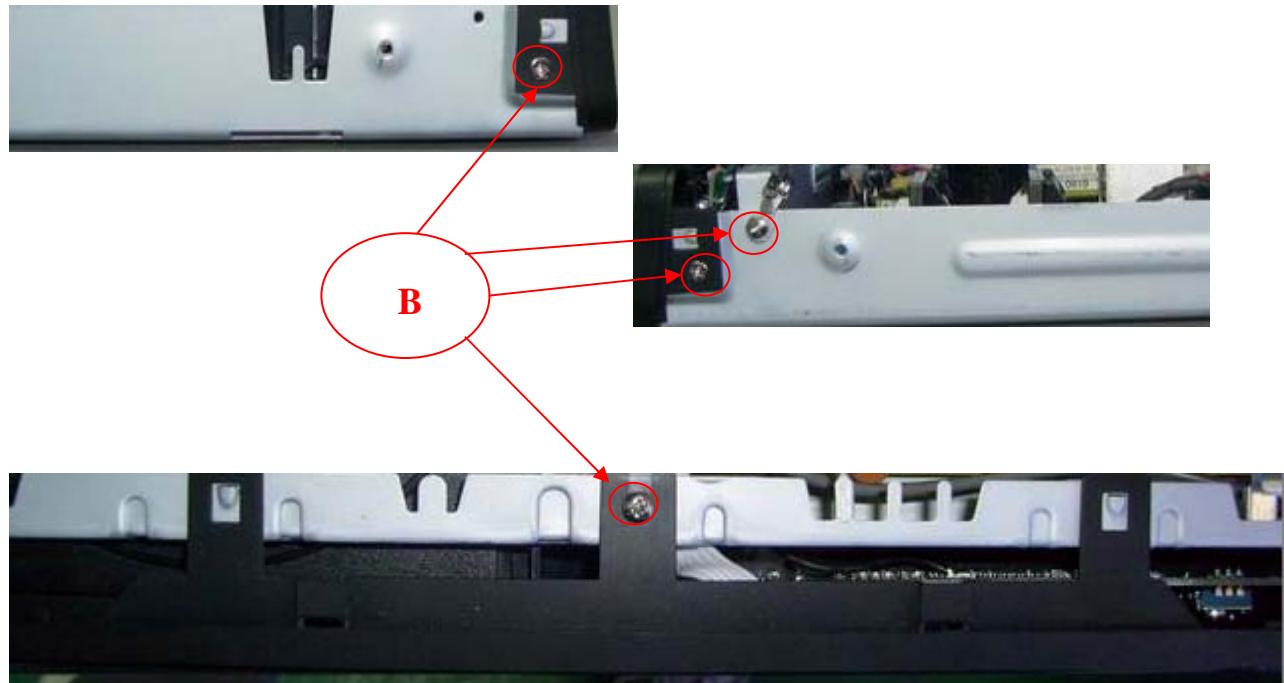


Figure 3-1

3-2. Release the lock "C" at the same time as shown figure 3-2.

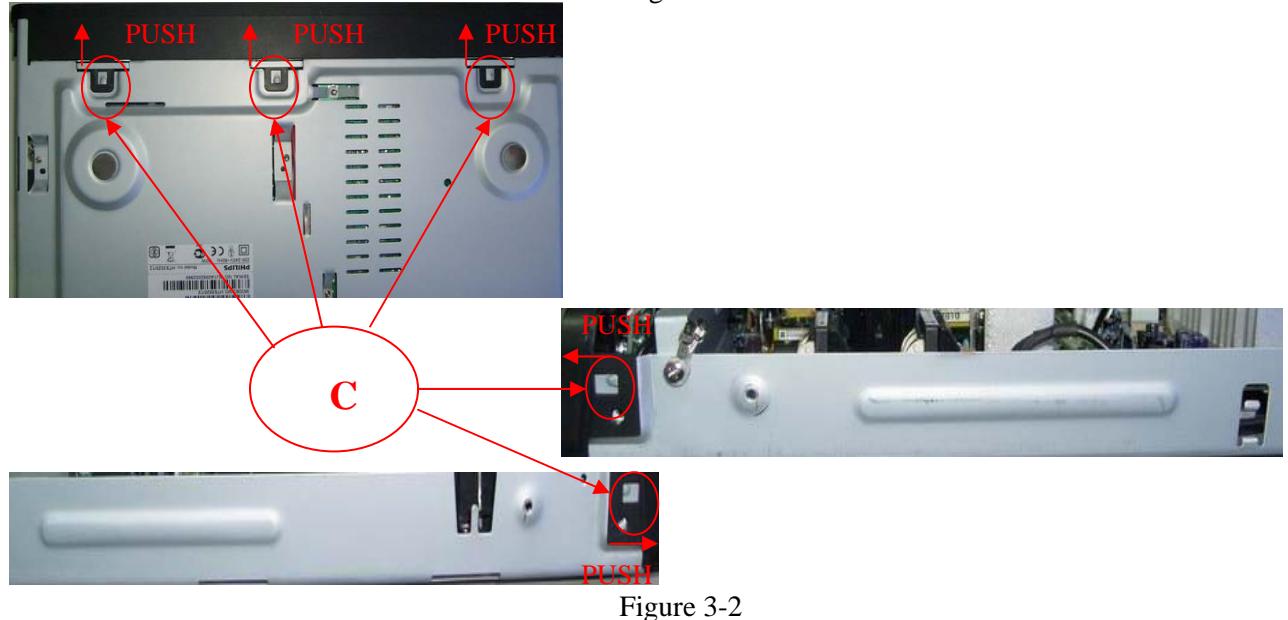


Figure 3-2

3-3. Loosen 5 screws "D" as shown in figure 3-3.

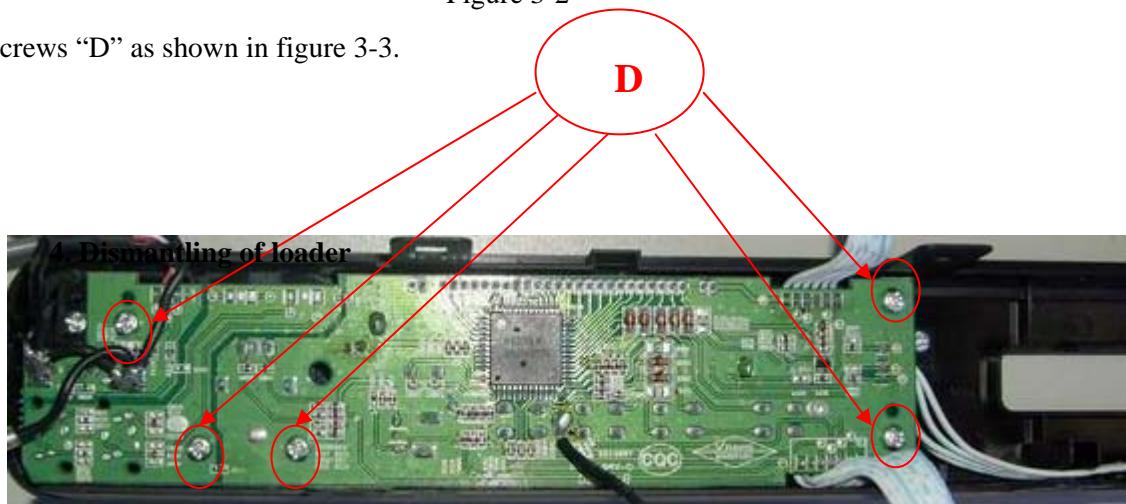


Figure 3-3

4-1. Loosen 4 screws "E" as shown in figure 4-1.

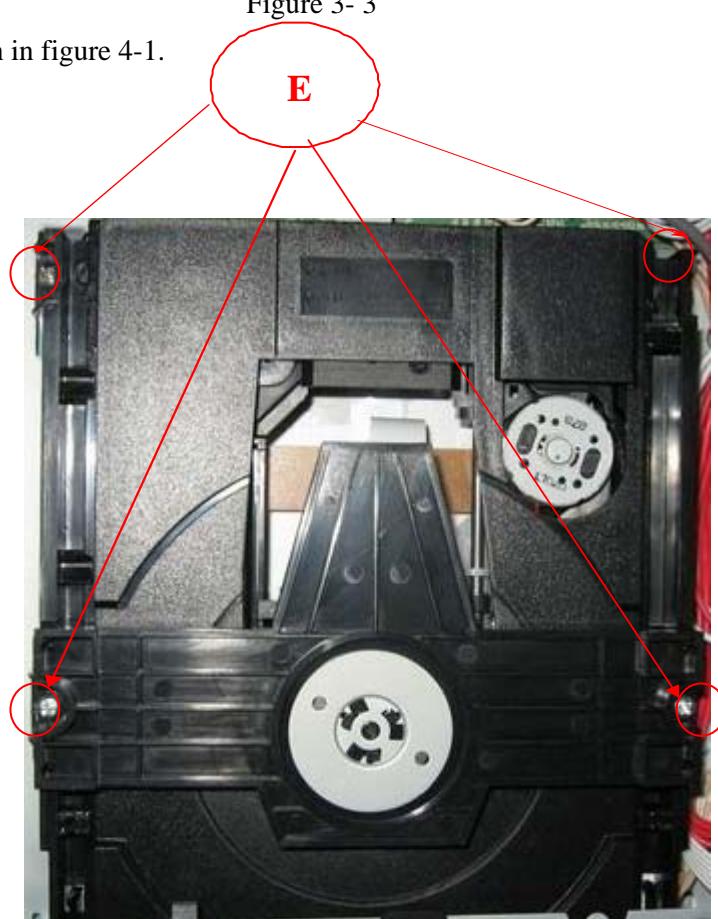


Figure 4-1

5. Dismantling of decode board

5-1. Loosen 5 screws as shown in figure 5-1.

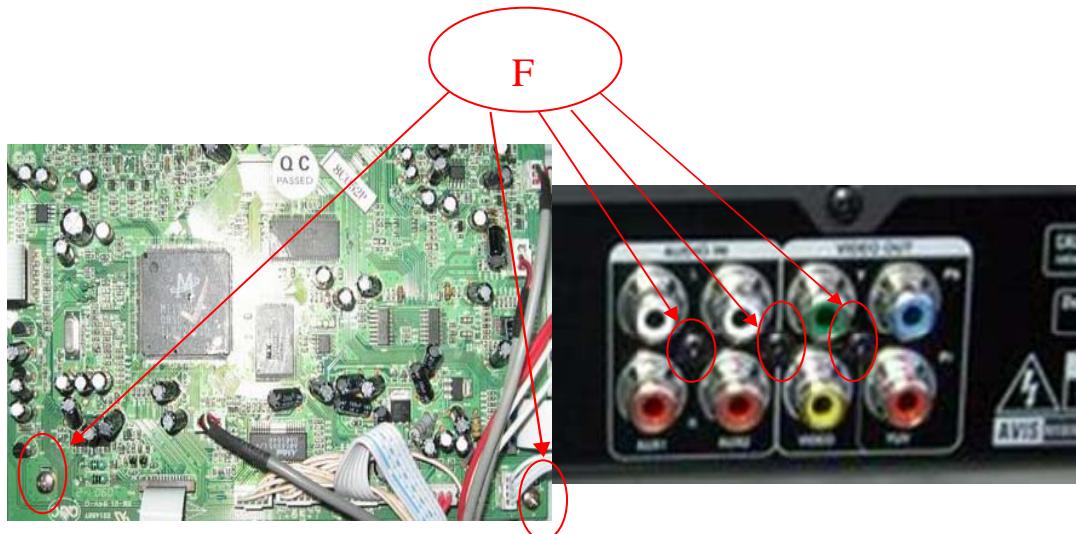


Figure 5-1

6. Dismantling of power board

6-1. Loosen 4 screws "G" as shown in figure 6-1.

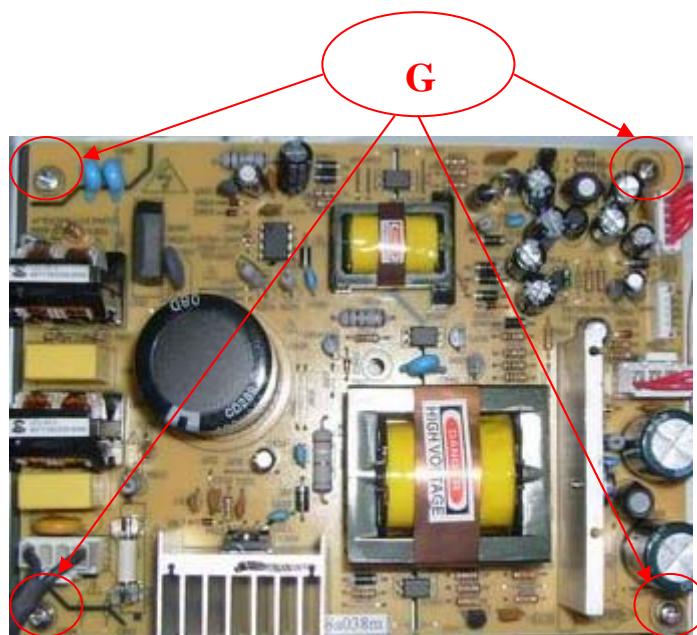


Figure 6-1

7. Dismantling of amplifier board

7-1. Loosen 4 screw "H" as shown in figure 7-1

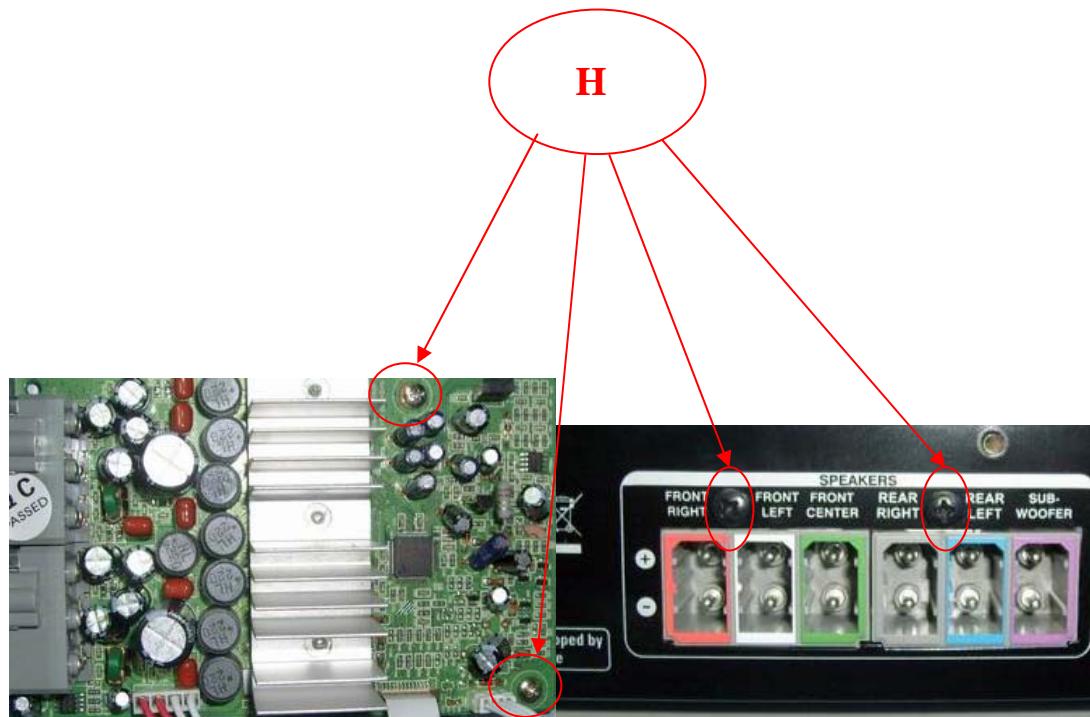


Figure 7-1.

8. Dismantling of tuner

8-1. Loosen 1 screws "I" as shown in figure 8-1.



Figure 8-1.

9. Dismantling of Led board

9-1. Loosen 2 screws "J" as shown in figure 9-1.

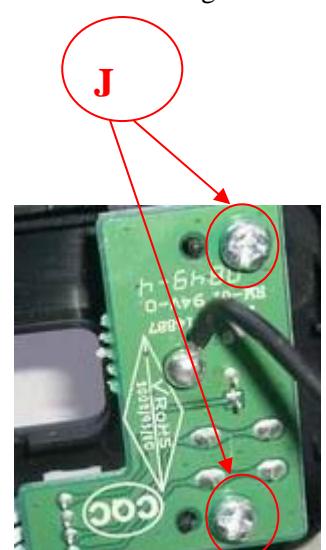
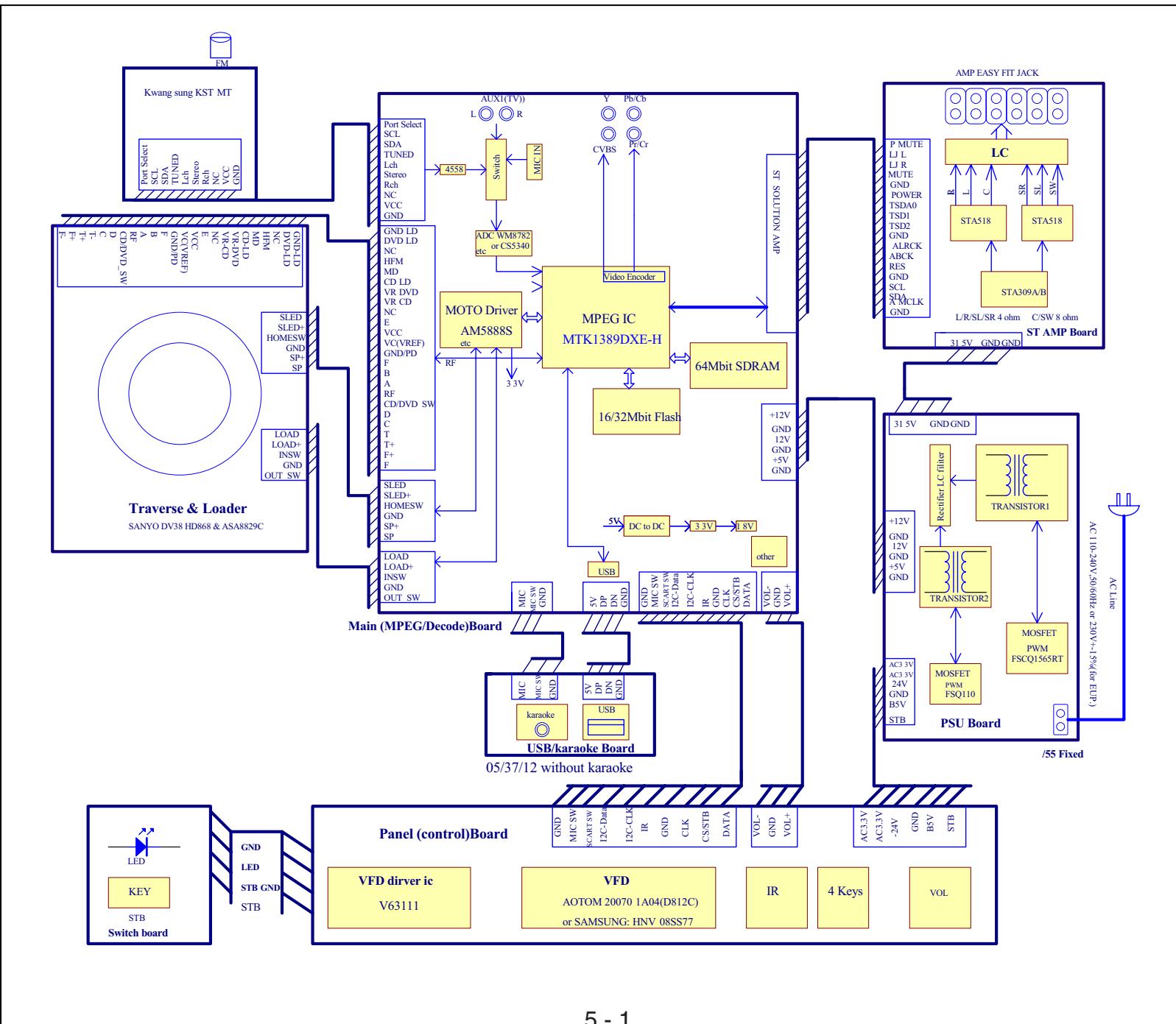


Figure 9-1.

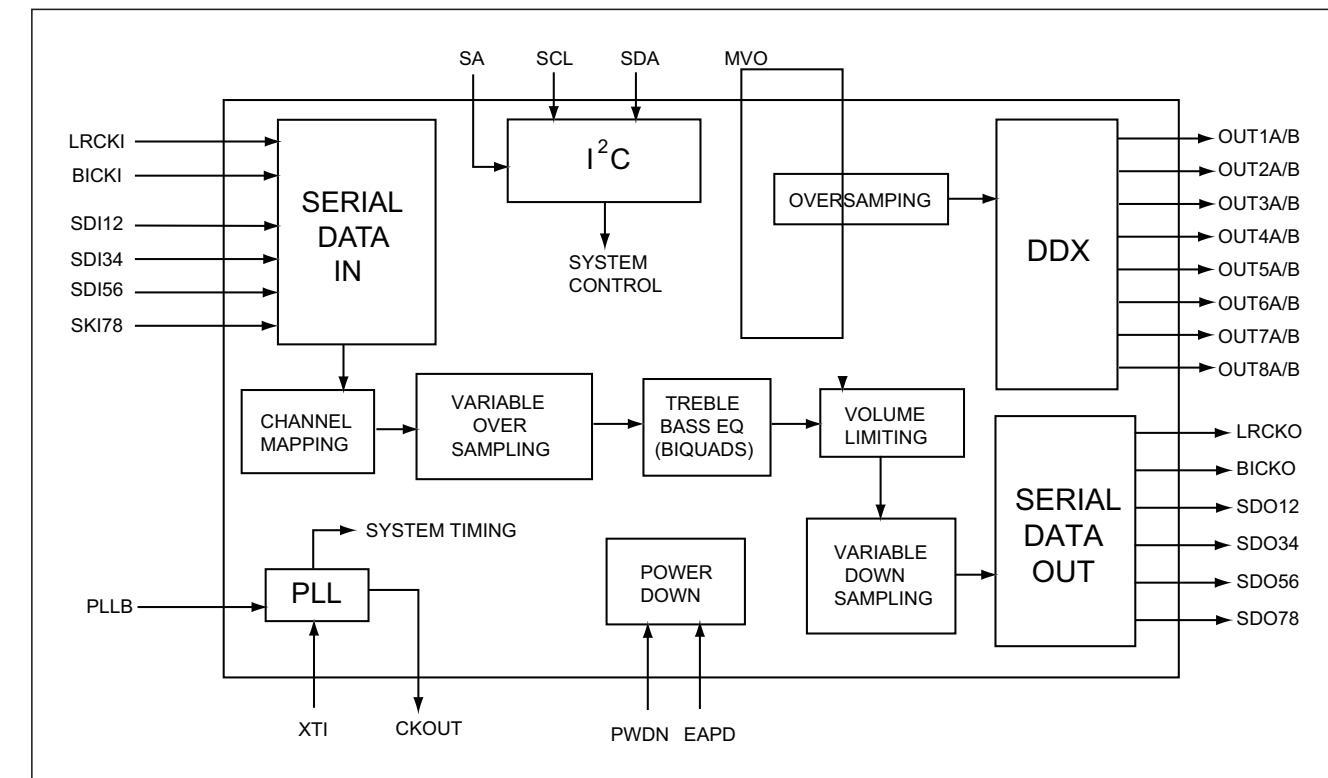


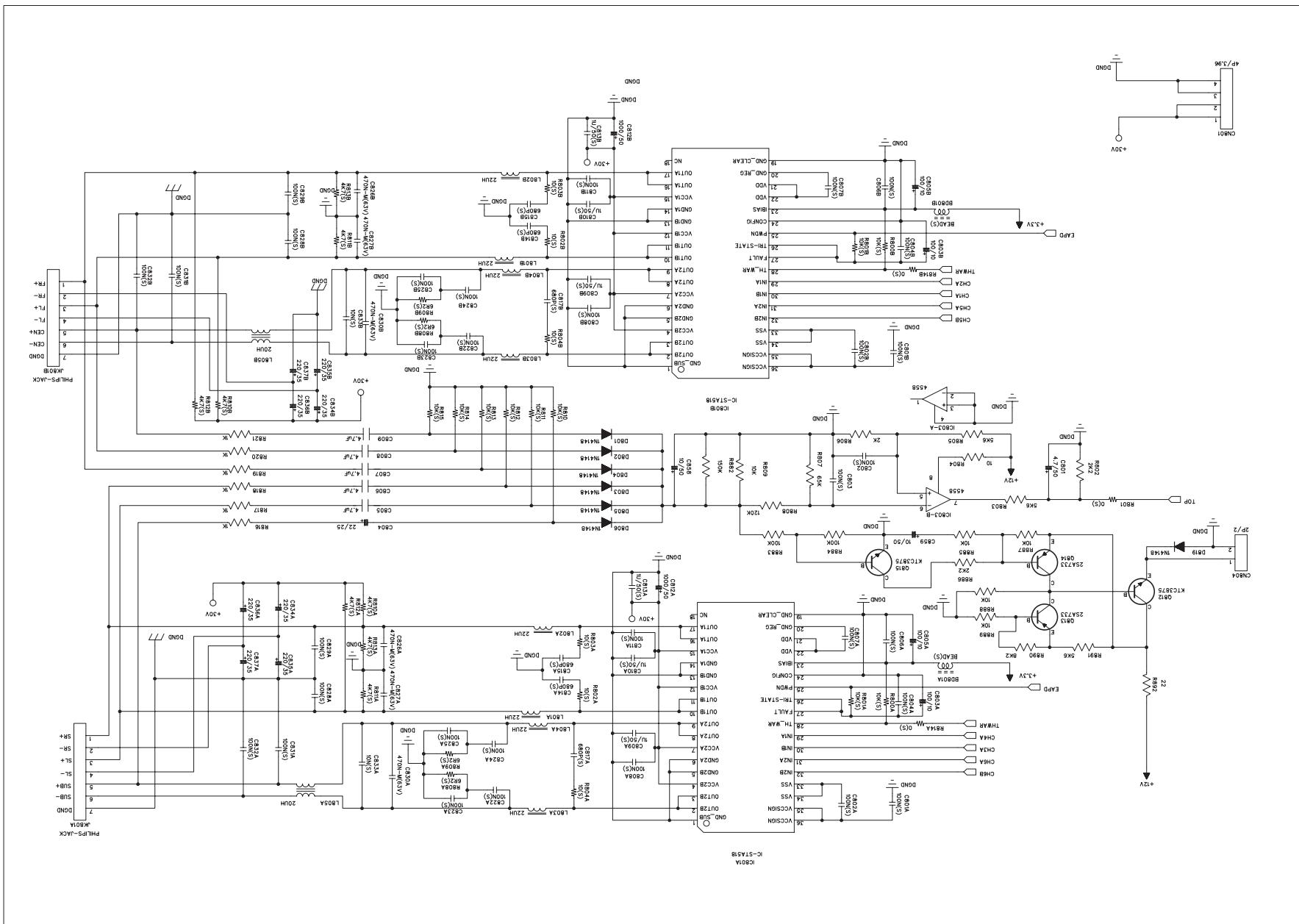
AMPLIFIER BOARD

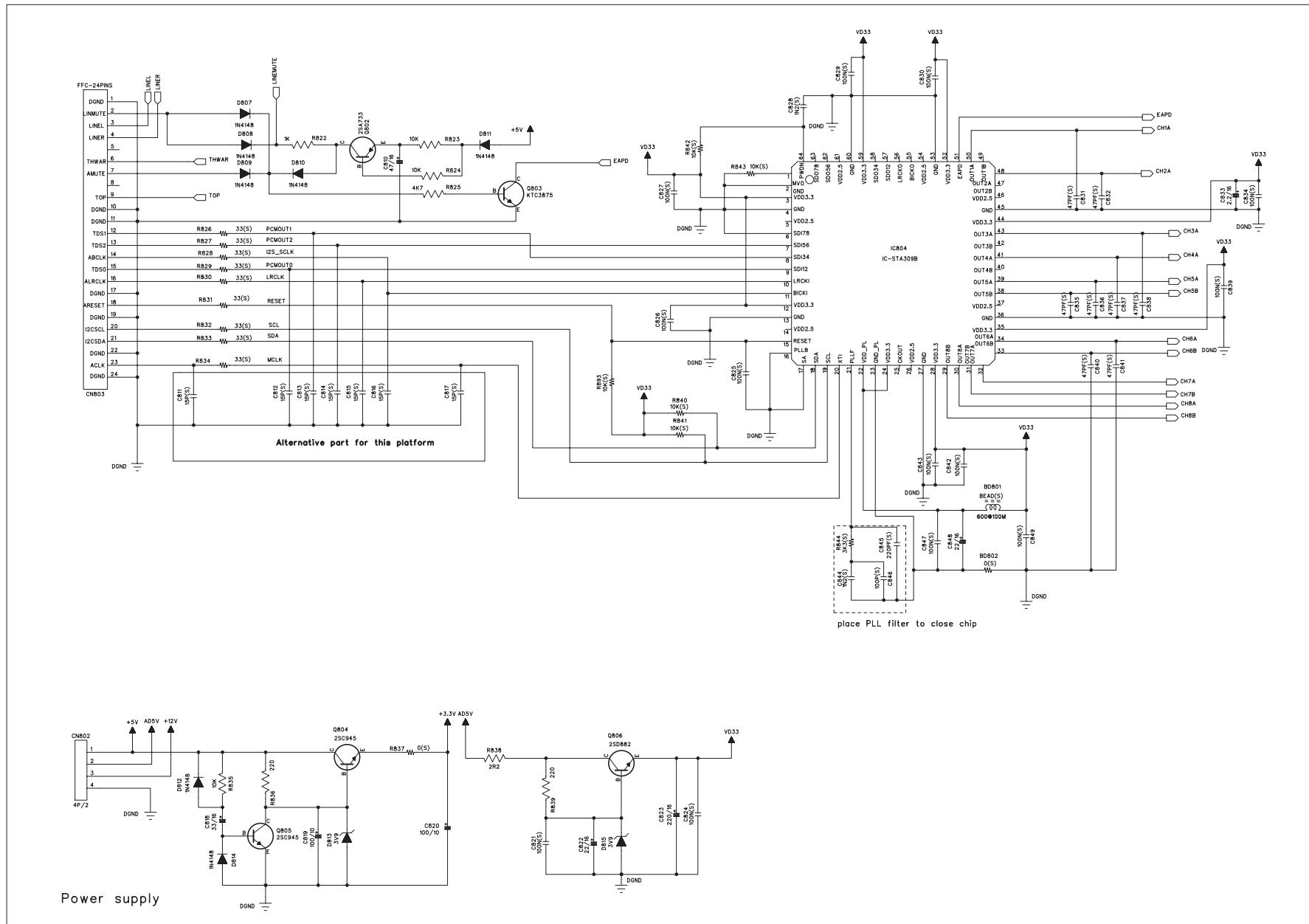
INTERNAL IC DIAGRAM - STA309A

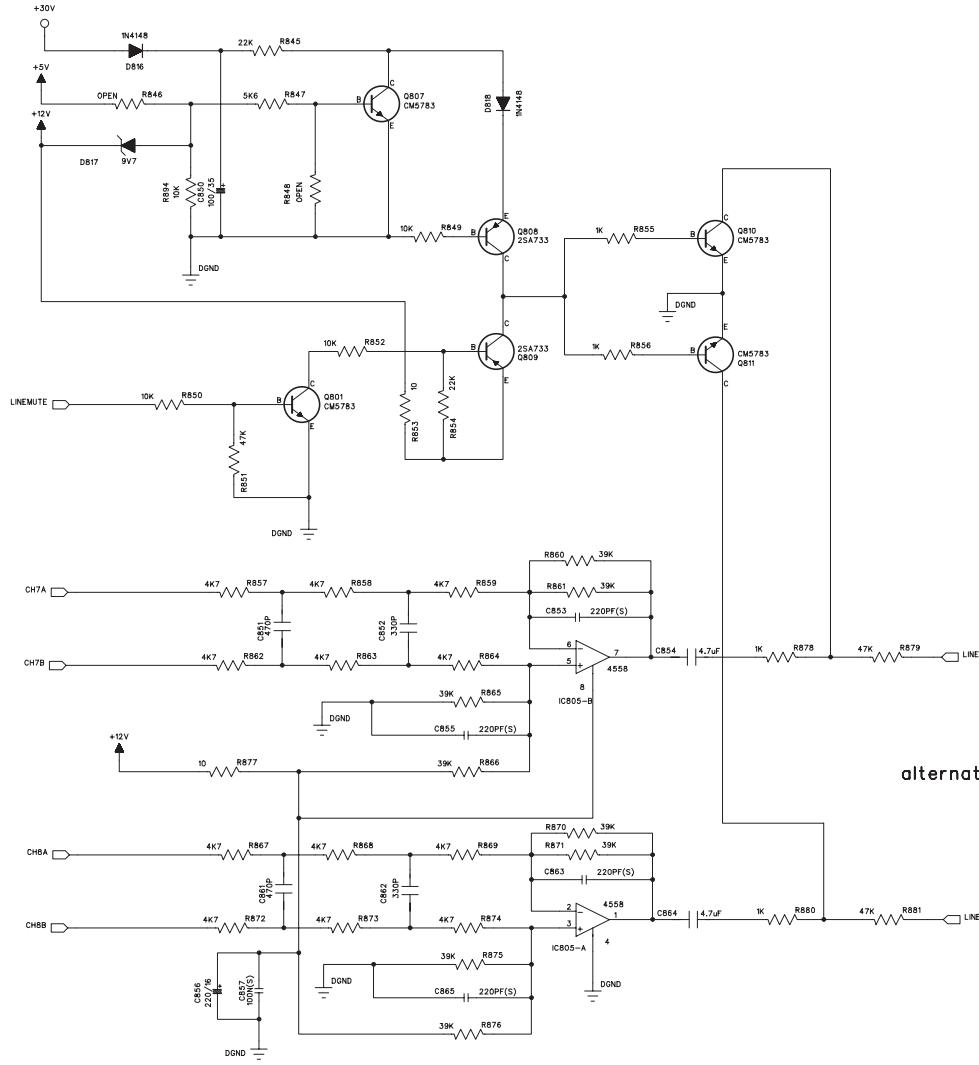
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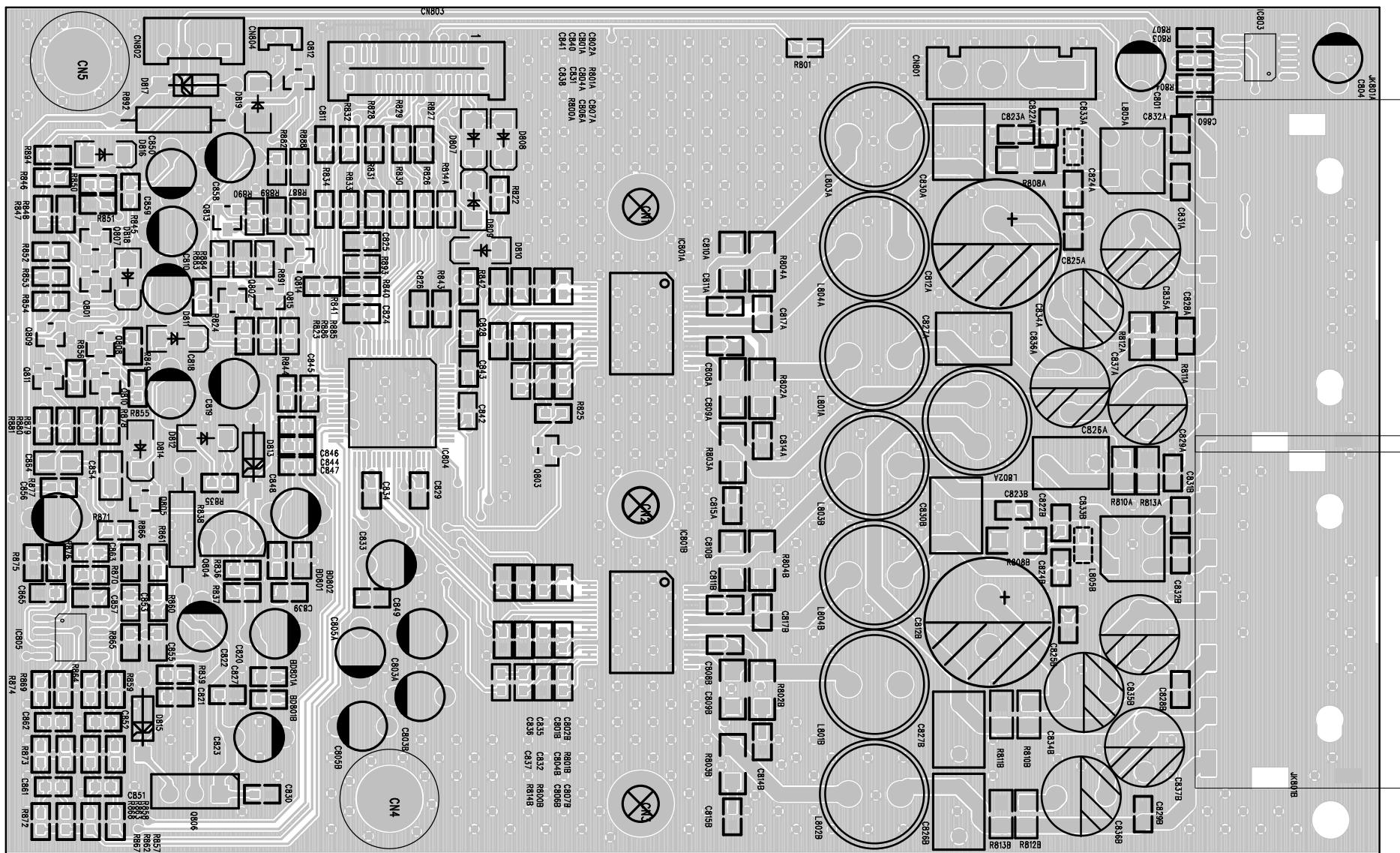


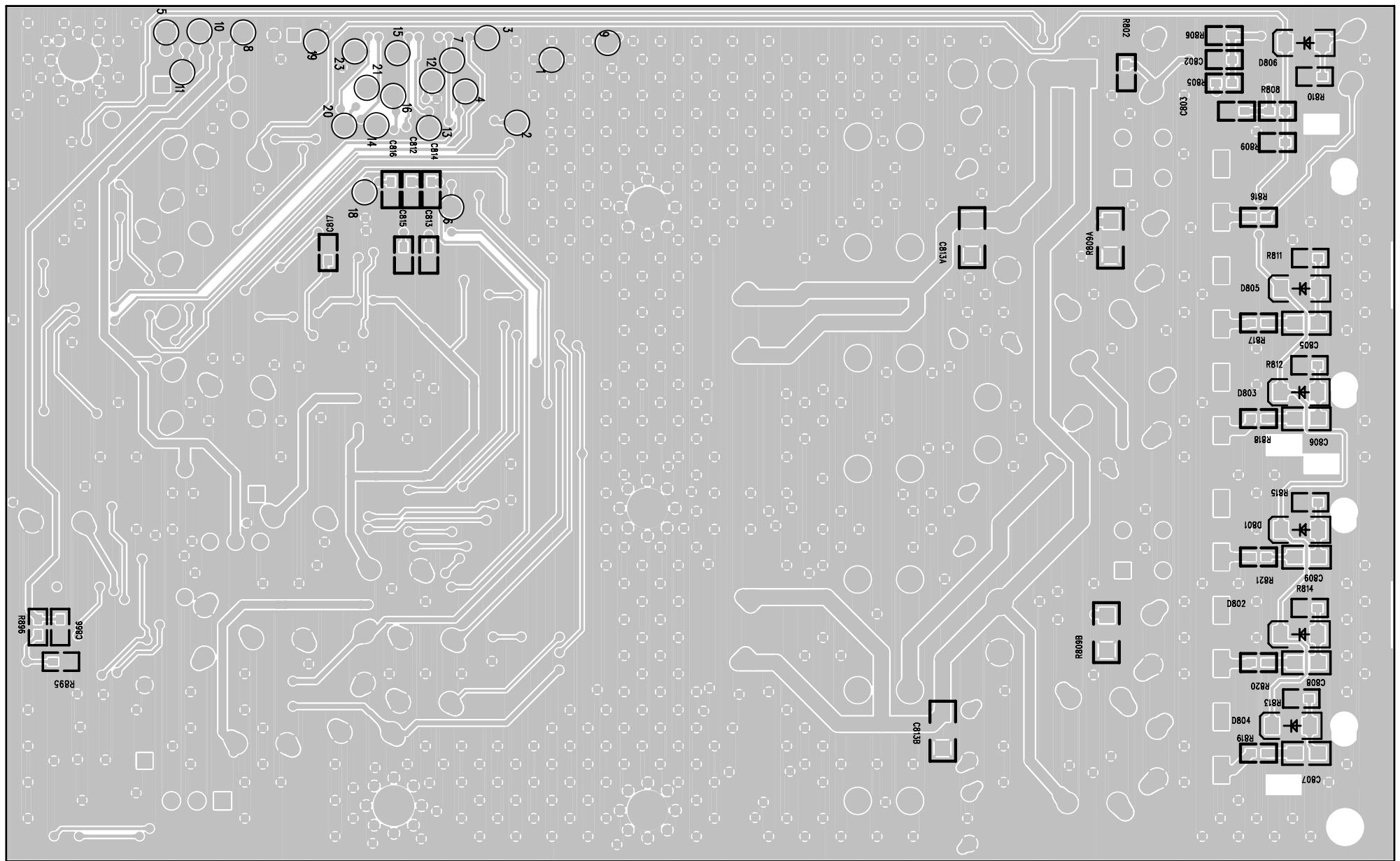






alternative part for this platform



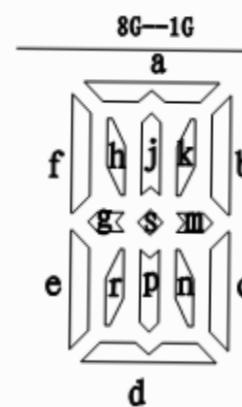
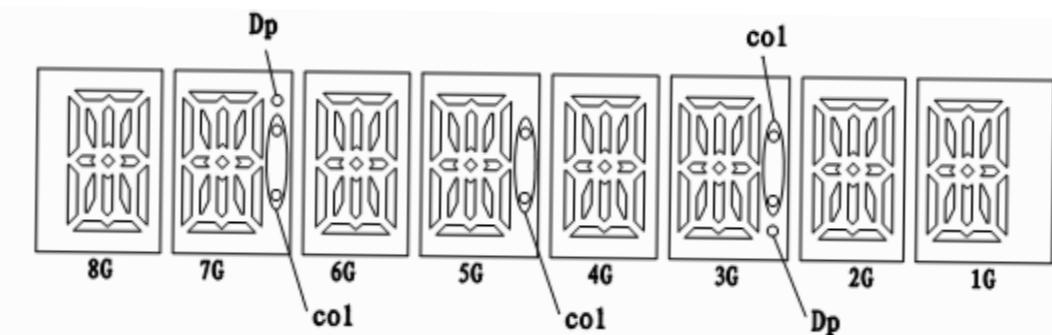


LED & KEY BOARD

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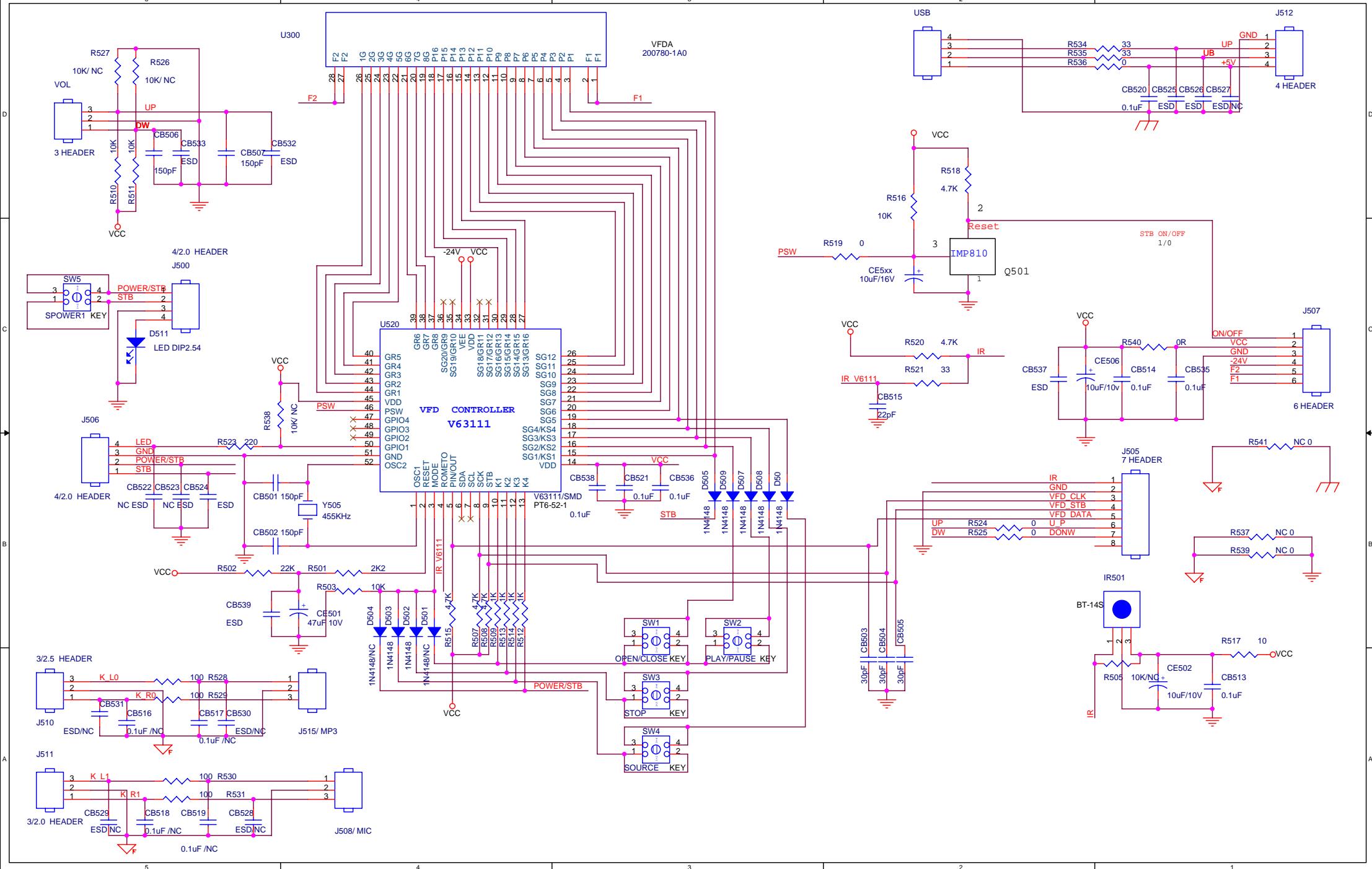
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FTD DISPLAY PIN ASSIGNMENT

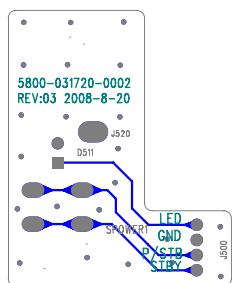


Colors of Illumination :
All is green (x=0. 250, y=0. 440).

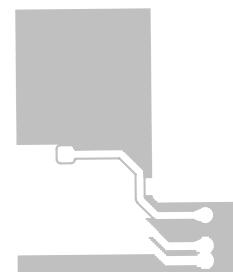
	8G	7G	6G	5G	4G	3G	2G	1G
P1	a	a	a	a	a	a	a	a
P2	j, p							
P3	h	h	h	h	h	h	h	h
P4	k	k	k	k	k	k	k	k
P5	b	b	b	b	b	b	b	b
P6	f	f	f	f	f	f	f	f
P7	m	m	m	m	m	m	m	m
P8	g	g	g	g	g	g	g	g
P9	c	c	c	c	c	c	c	c
P10	e	e	e	e	e	e	e	e
P11	r	r	r	r	r	r	r	r
P12	n	n	n	n	n	n	n	n
P13	d	d	d	d	d	d	d	d
P14		Dp		col		col		
P15	s	s	s	s	s	s	s	s
P16		col				Dp		



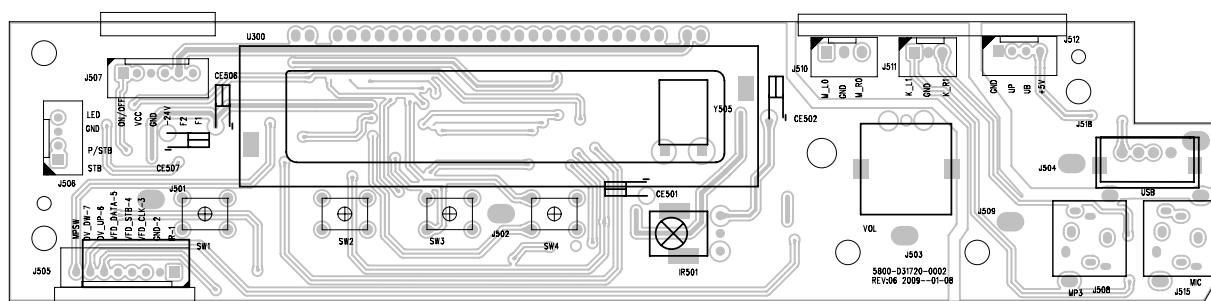
LED BOARD TOP VIEW



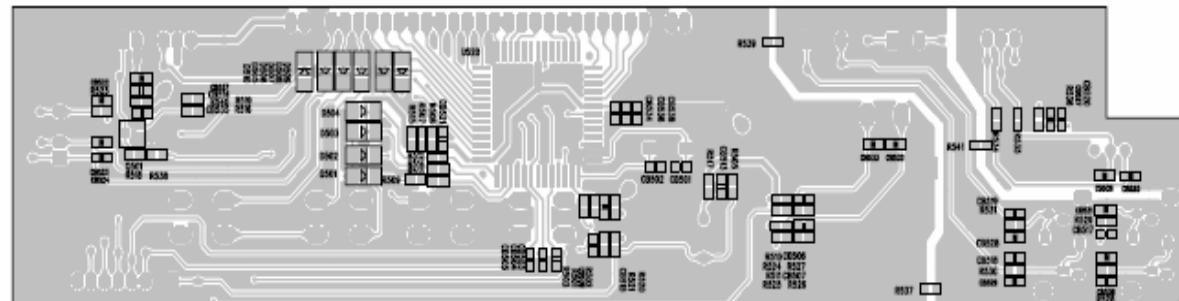
LED BOARD BOTTOM VIEW



KEY BOARD TOP VIEW



KEY BOARD BOTTOM VIEW

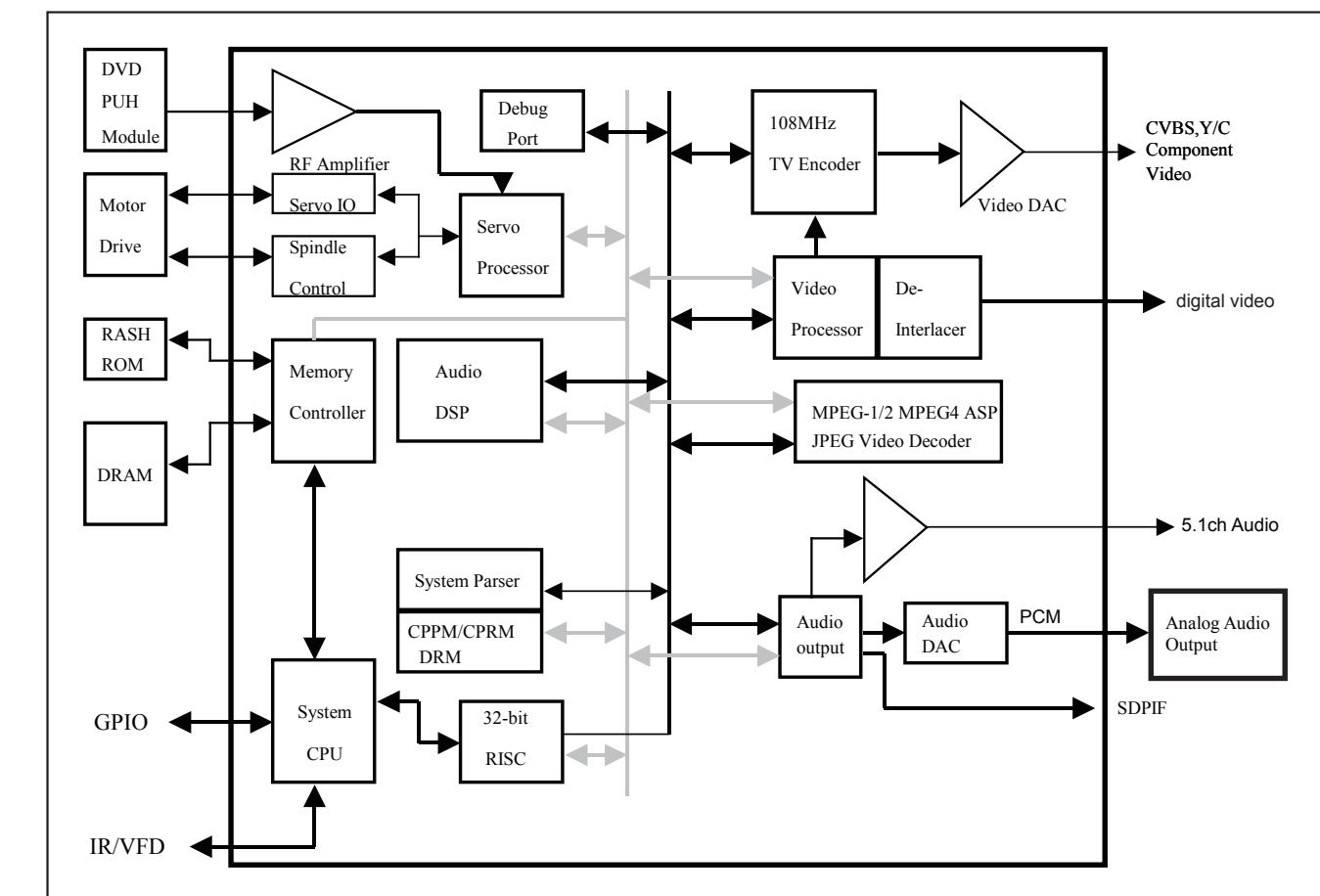


DECODE BOARD

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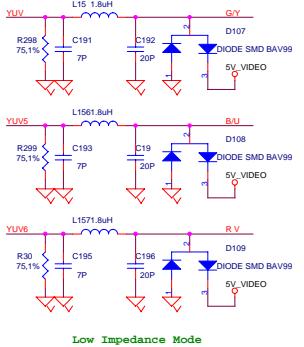
INTERNAL IC DIAGRAM - MT1389HD



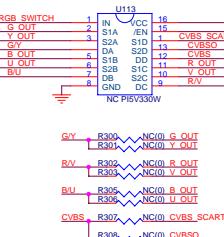
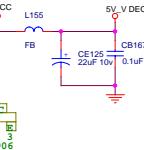
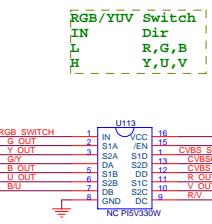
[2] YUV[3..6] >> YUV[3..6]
 [2] MUTE_DAC >> MUTE_DAC

 [2] FS0 >> FS0
 [2] FS1 >> RGB_SWITCH
 [5] SCART_L >> SCART_L
 [5] SCART_R >> SCART_R
 [5] A_MUTE >> A_MUTE

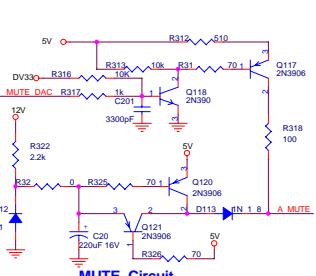
 [1..2..5] AVCC << AVCC
 [1..5..6] 12V << 12V
 [1..2..3..5..6] DV33 << DV33
 [1..2] 5V << 5V
 [5] SCART_L_IN << SCART_L_IN
 [5] SCART_R_IN << SCART_R_IN



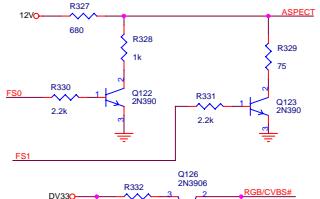
RGB_SWITCH: 0--->RGB,
1--->CVBS/YUV



Low Impedance Mode



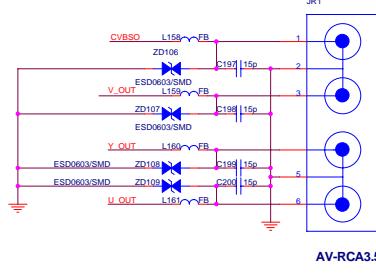
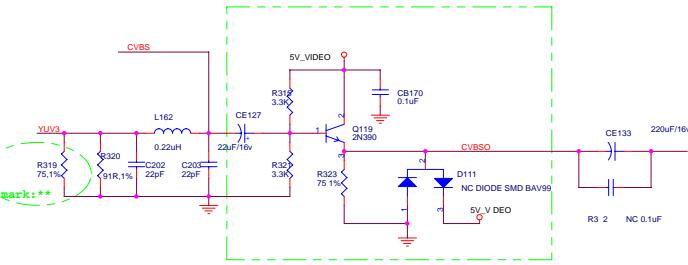
MUTE Circuit



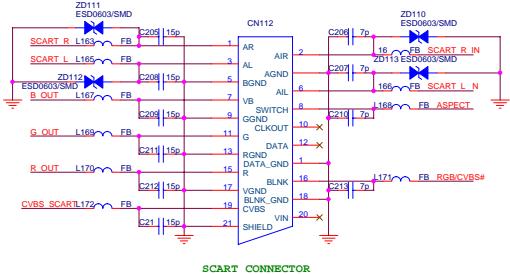
SCART CONTROL

FS0	FS1	
PIN158	PIN157	RT1159
0	0	4 3 / USB
0	1	
1	0	16 9
1	1	STB / AUX IN / MP3 IN / SCART IR / FM IN

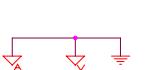
Only when both signal CVBSO & SCART_CVBS need output, then the parts mark *** will need to be added.



AV-RCA3.5



RGB_SWITCH#: 1~3V RGB, 0~0.4V CVBS

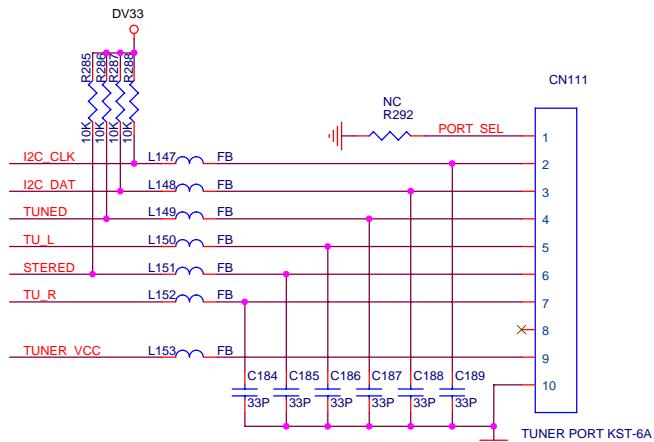
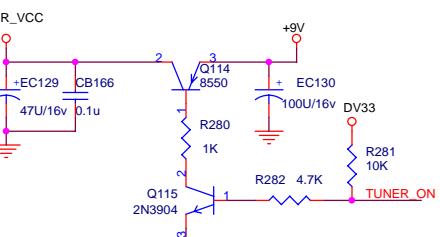
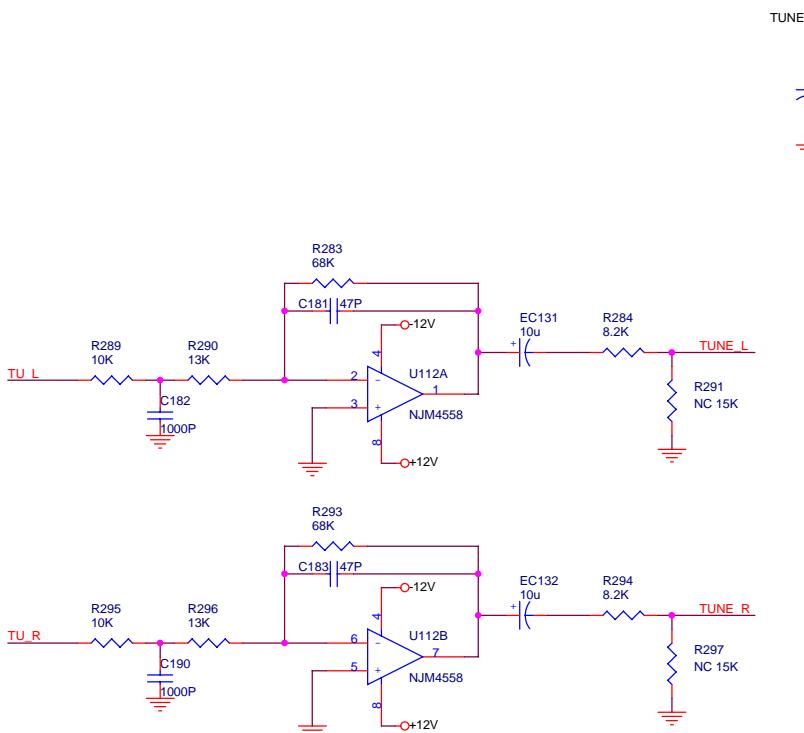


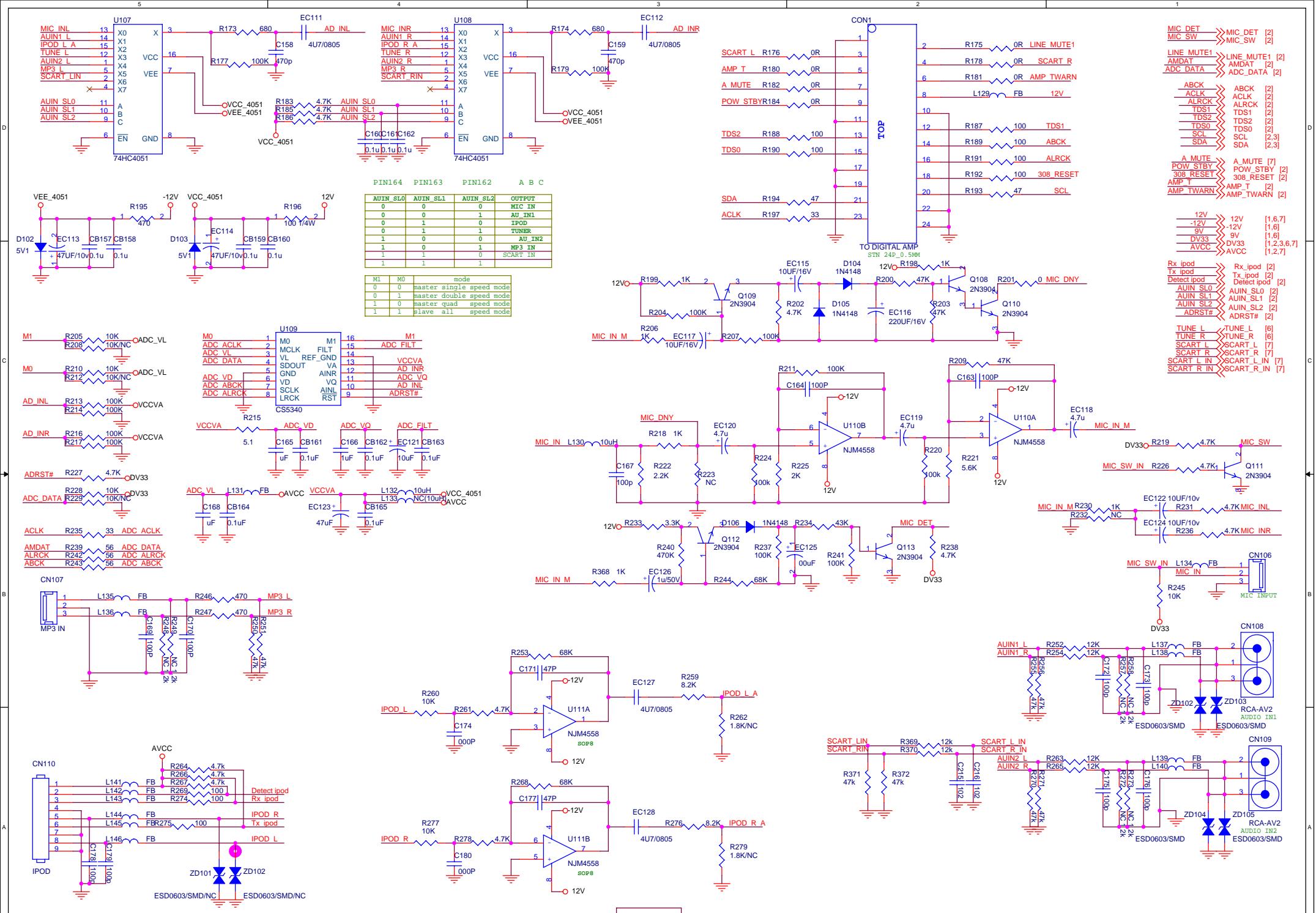
Amute

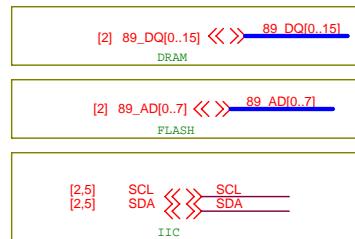
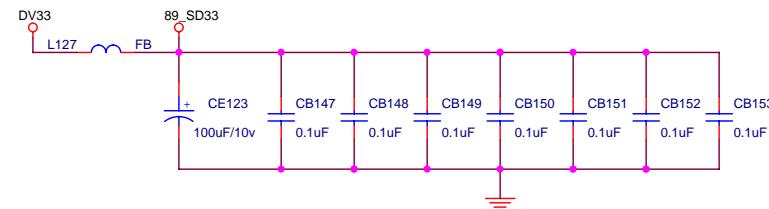
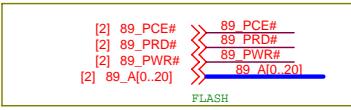
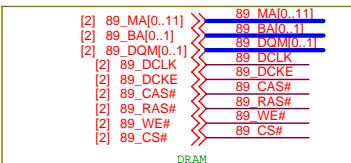
[2] TUNER_ON >> TUNER_ON
 [2] TUNED >> STERED
 [2] STERED >> I2C CLK
 [2] I2C_CLK >> I2C DAT
 [2] I2C_DAT >> I2C DAT

TUNE_L >> TUNE_L [5]
 TUNE_R >> TUNE_R [5]

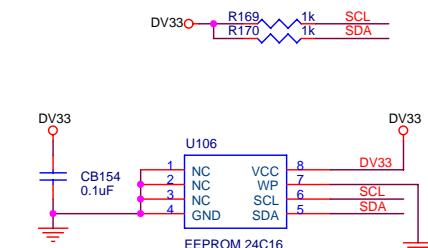
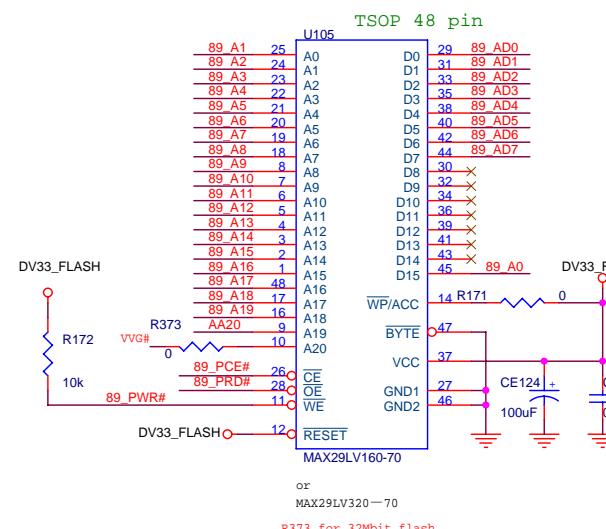
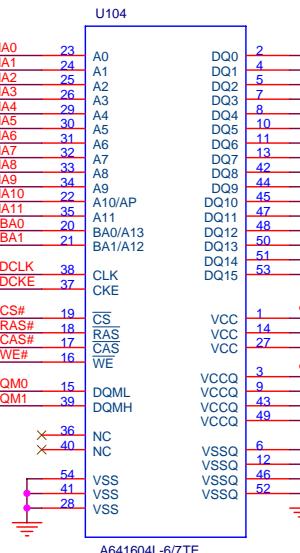
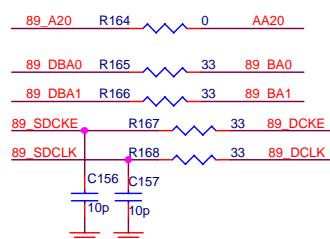
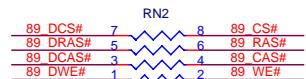
+9V >> +9V [1]
 DV33 >> DV33 [1,2,3,5,7]
 +12V >> +12V [1,5,7]
 -12V >> -12V [1,5]

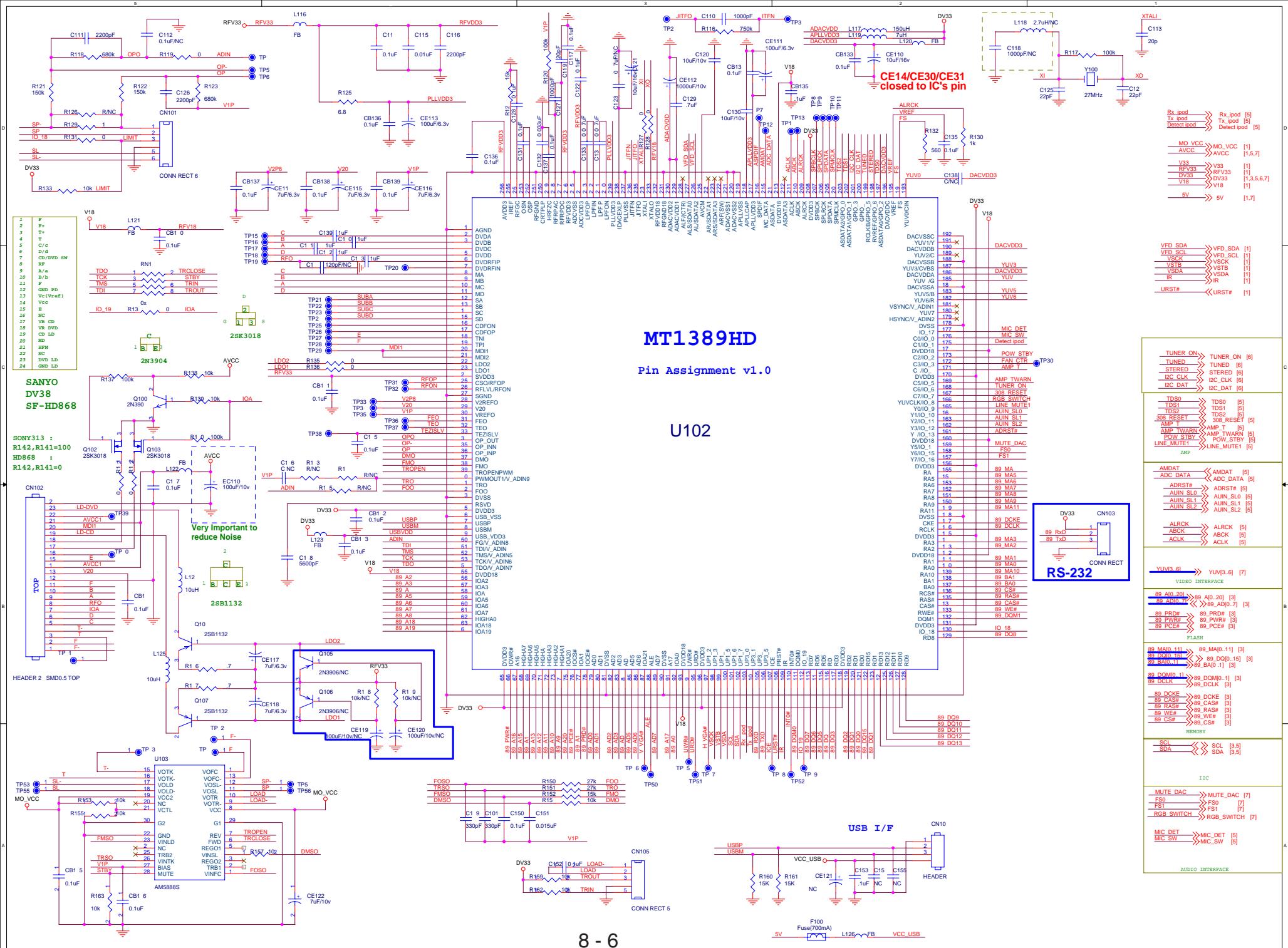




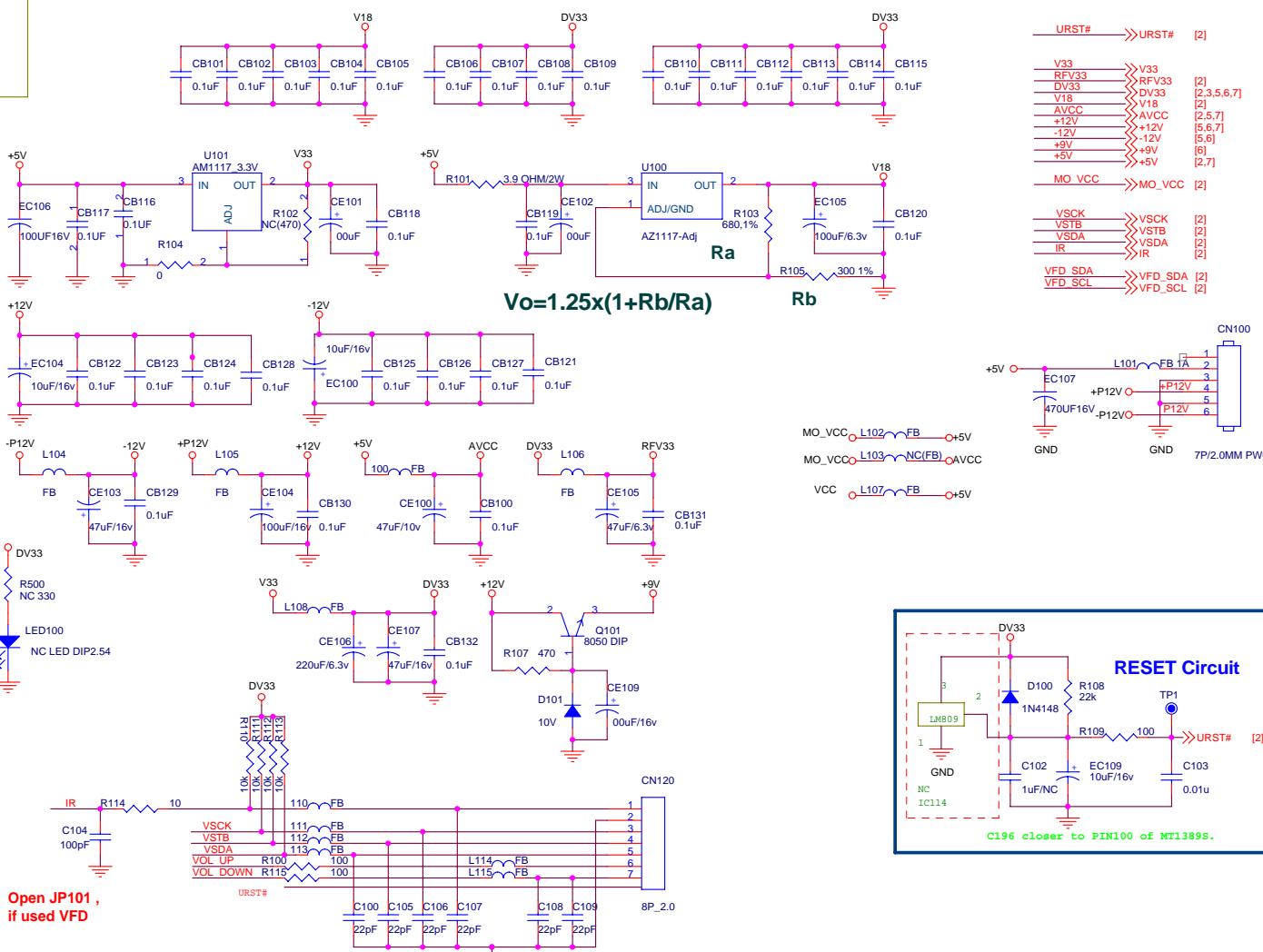


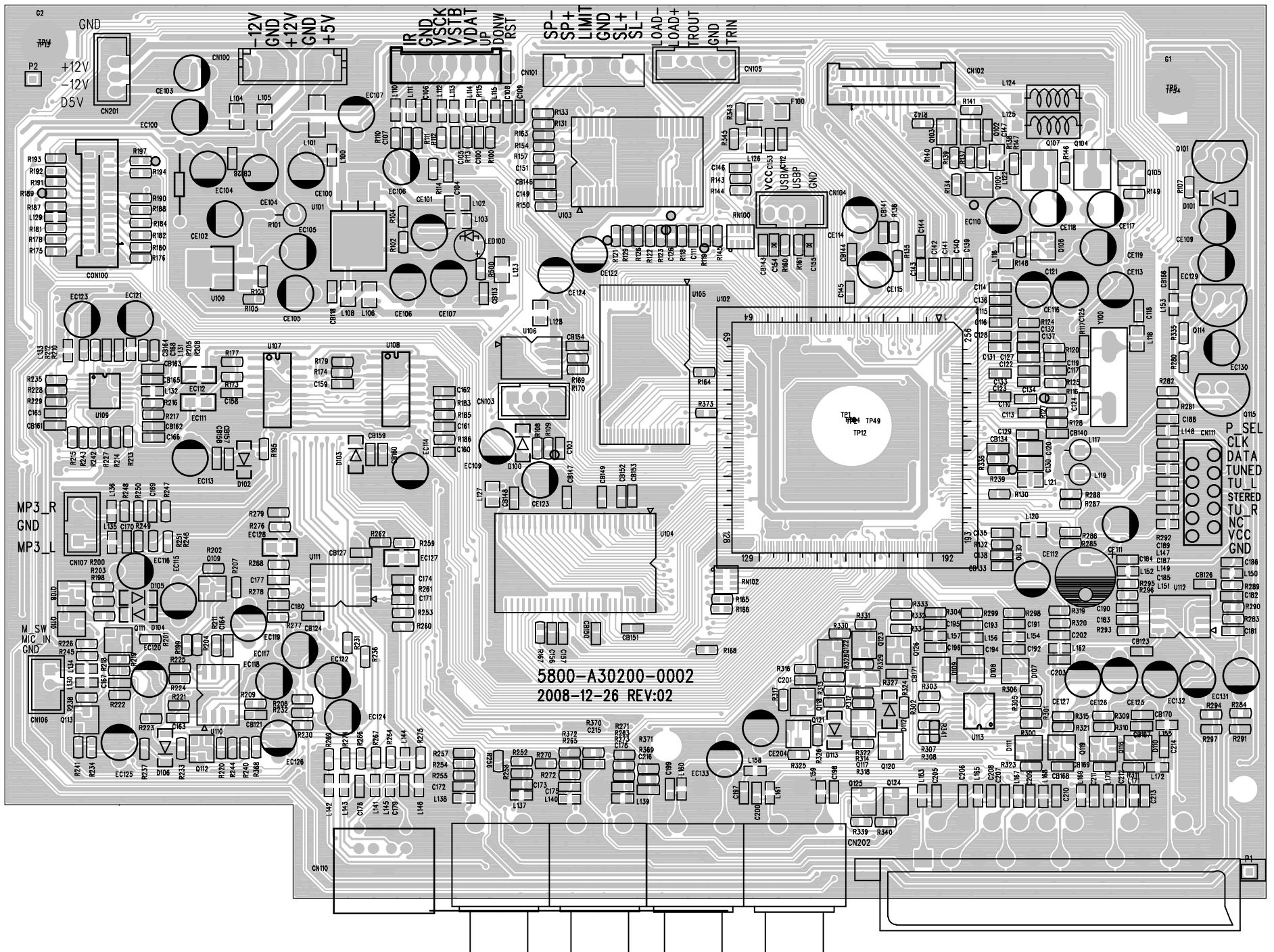
DV33 >> DV33 [1,2,5,6,7]

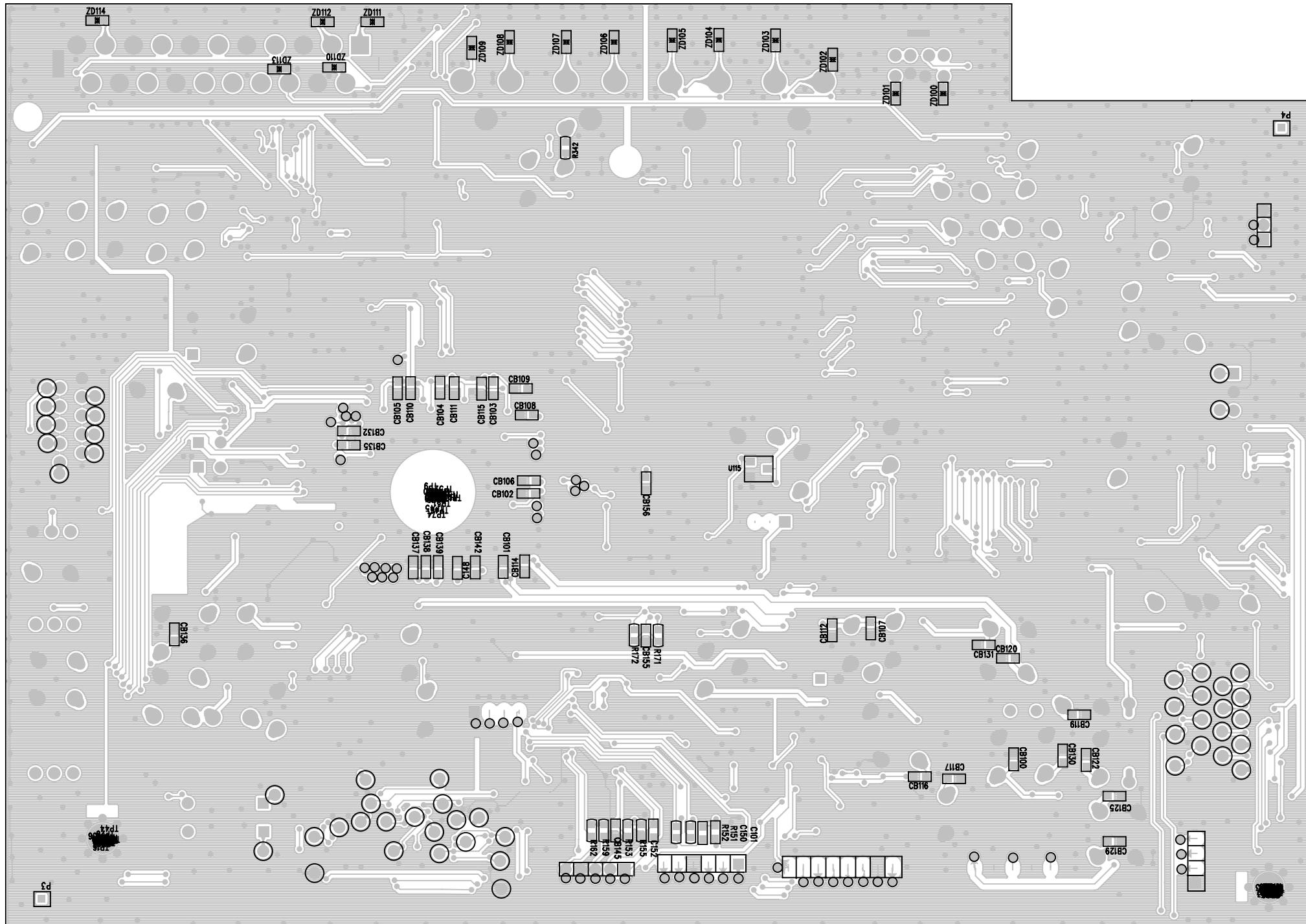




NAME	TYPE	DEVICE
VCC/+5V	Digital 5V	SUPPLY
DV33	Digital 3.3V	MT1389HD
RFV33	Servo 3.3V	MT1389HD
AV33	Laser Diode 3.3V	
V18	Digital 1.8V	MT1389HD
SD33	Digital 3.3V	SDRAM
+12V	Audio +12V	OP AMP.
-12V	Audio -12V	OP AMP.
AVDD5	Audio 5V	Audio DAC
DVDD3	Audio 3.3V	Audio DAC
MCU_3V3	Nxp Mcu 3.3V	MCU





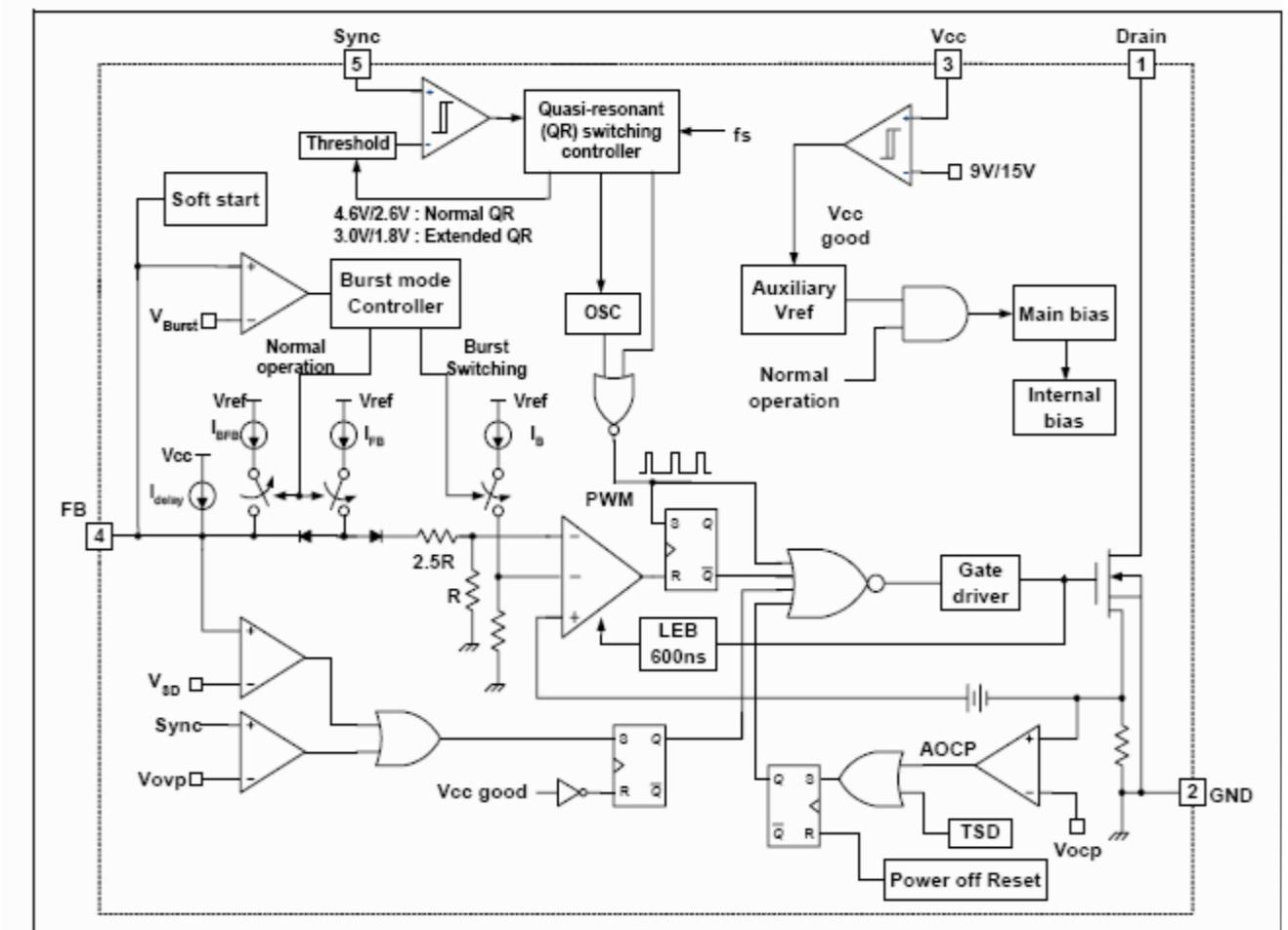


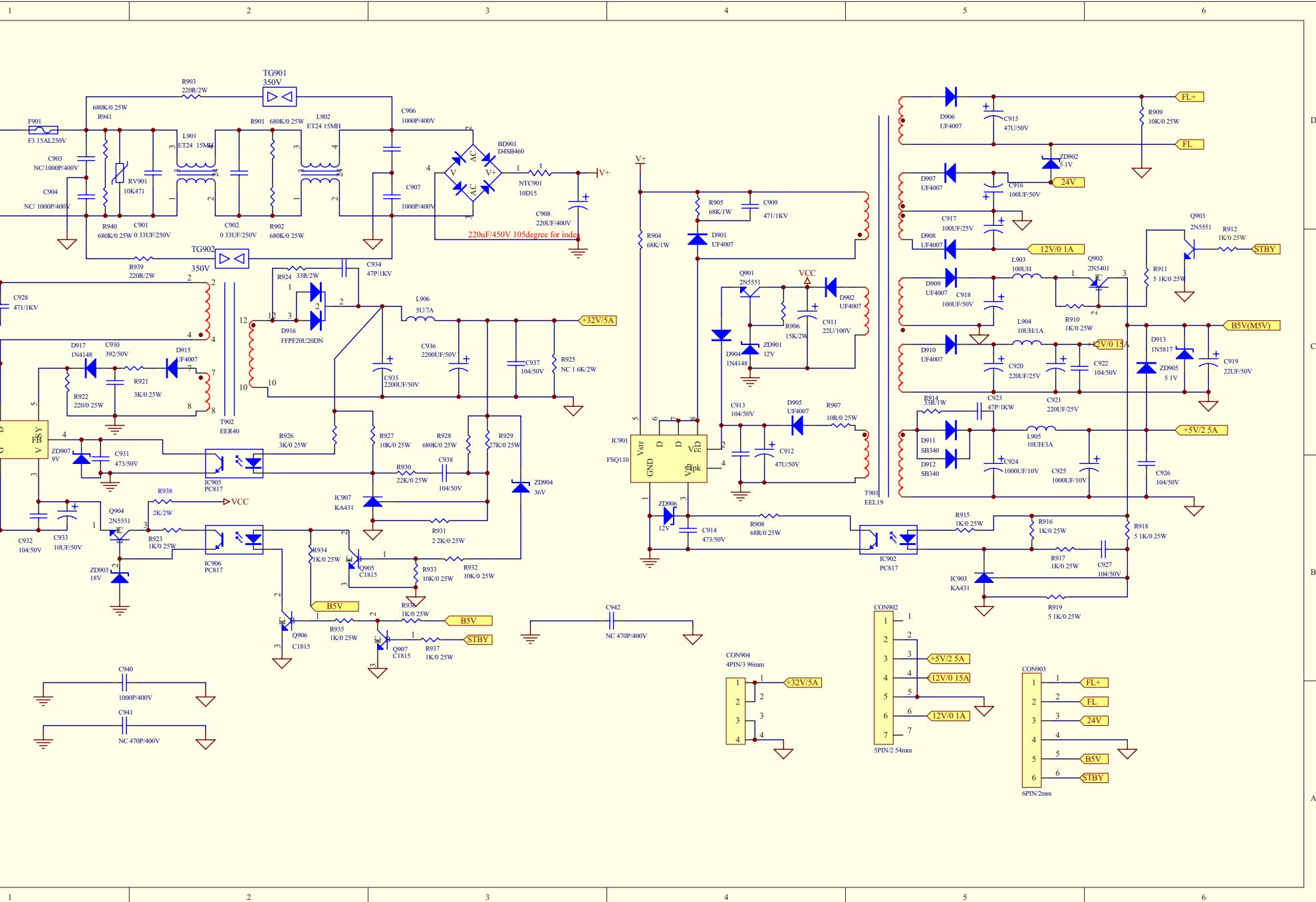
POWER BOARD

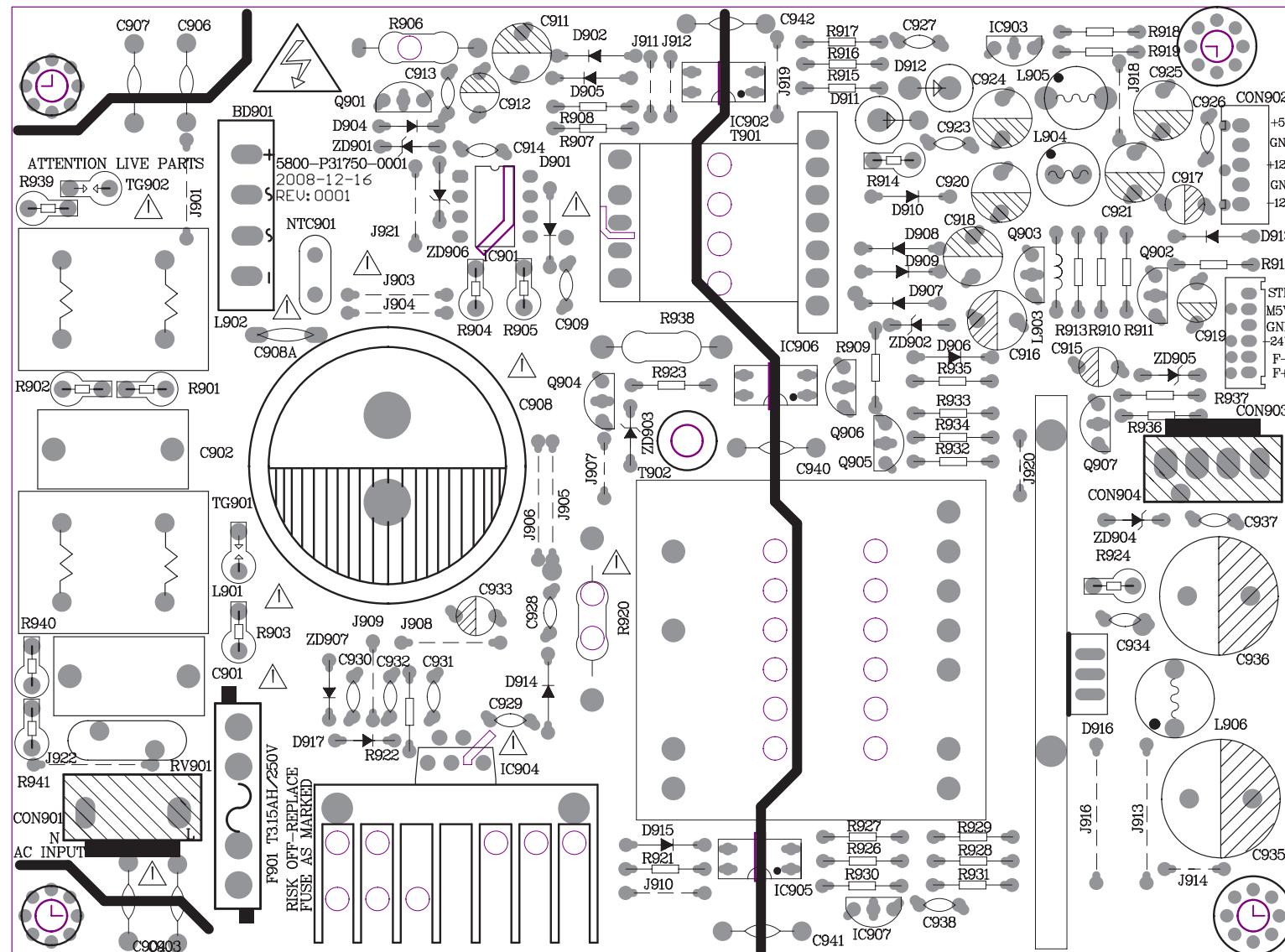
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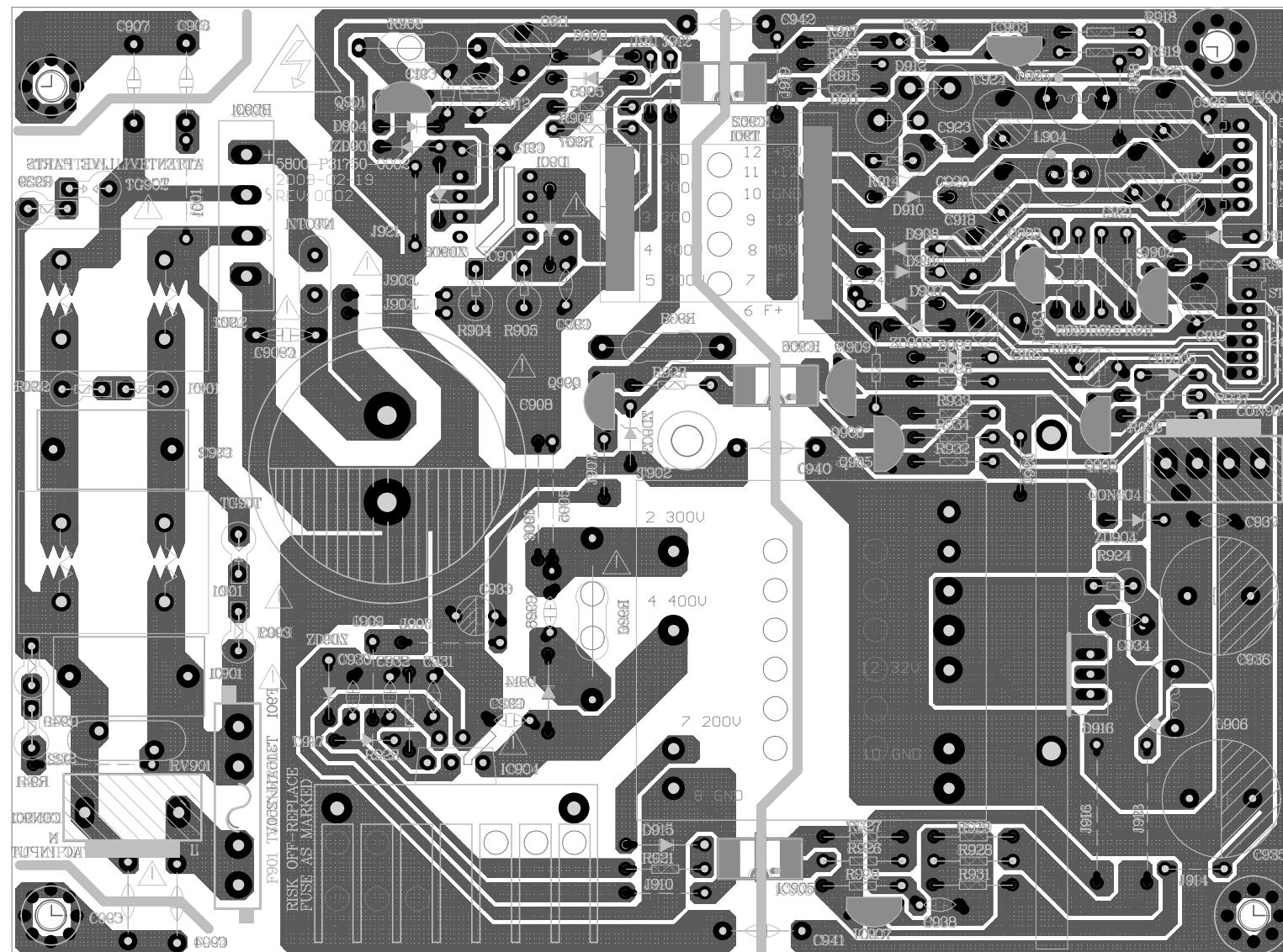
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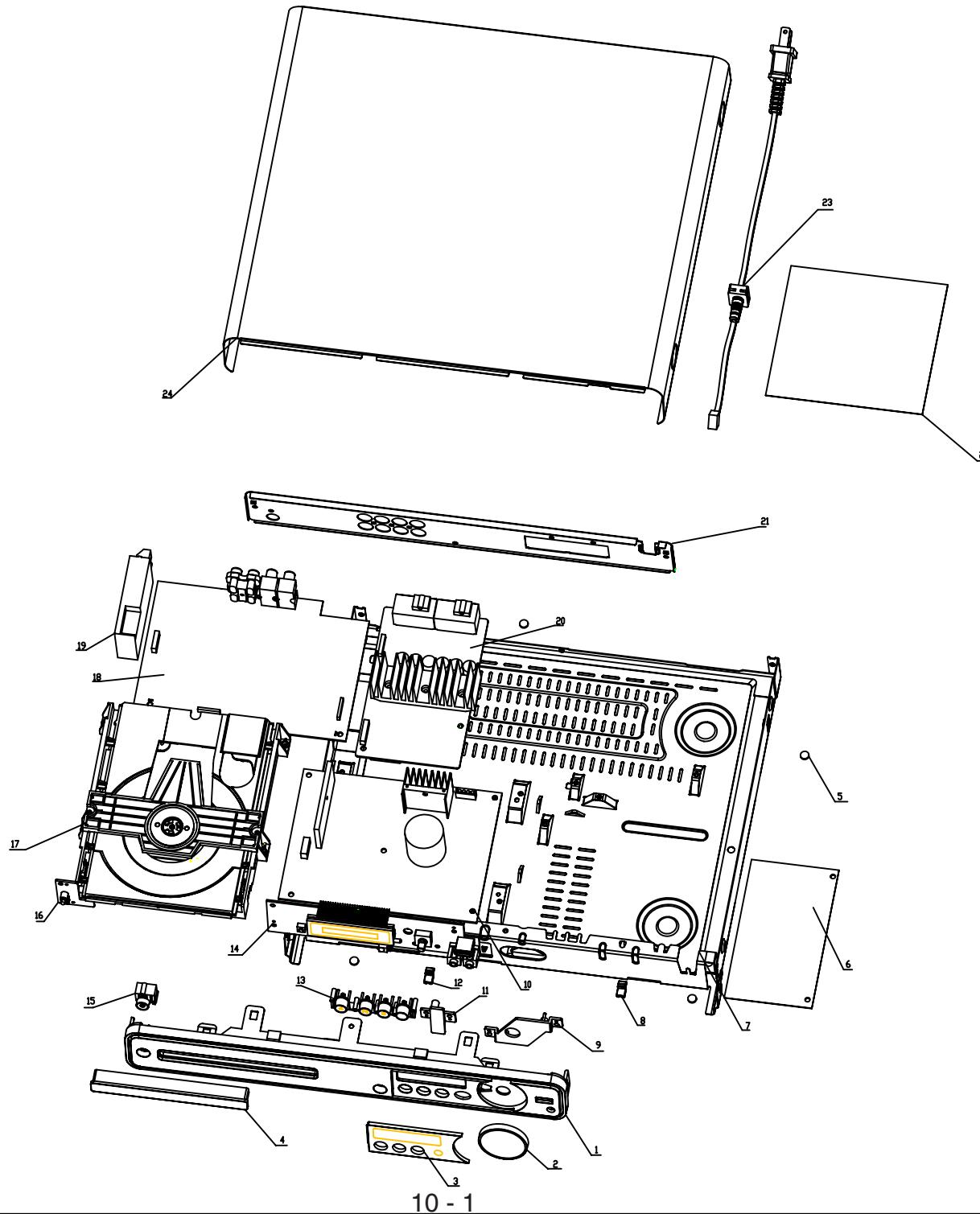
INTERNAL IC DIAGRAM - FSC1565RT











LOC.	Alt.	12NC	Safety	Description
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POWER BOARD

L903	996500040253	PEAKING CO L 100uH	/-10%	
L904	996510022165	CHOKE COIL 10UH	/-10% ⁷	5MMX9.5
L905	996510022163	CHOKE COIL5UH	/-15% ⁷	9MMX21MM P
L906	996510022186	CHOKE COIL 10UH	/-10% ⁷	5MMX9.5
NTC901	996510016185	NTC THERMISTOR	RESISTOR 5D2-10	
PCB	996510028191	MP P.C.BORD	140.00X162.00mm R	
Q901	996510028157	TRANSISTOR 2N5551	PNP TO-92 PA	
Q902	996510028173	TRANSISTOR 2N5401	PNP TO-92 PA	
Q903	996510028157	TRANSISTOR 2N5551	PNP TO-92 PA	
Q904	996510028157	TRANSISTOR 2N5551	PNP TO-92 PA	
Q905	996500040232	TRANSISTOR 2SC1815Y	/2PC1815	
Q906	996500040232	TRANSISTOR 2SC1815Y	/2PC1815	
Q907	996500040232	TRANSISTOR 2SC1815Y	/2PC1815	
R920	996510022203	METAL OX DE FILM	RESISTOR39K O	
RV901	996510016184	VARISTOR 10D471K	10%	
T901	996510022226	SWITCHING TRANSFORMER	BK-35-L0	
T902	996510028187	SWITCHING TRANSFORMER	BCK-60-L	
TG901	996510028163	GAS DISCHAR GE TUBE	DSP-301N-C	
TG902	996510028163	GAS DISCHAR GE TUBE	DSP-301N-C	
ZD901	996500040575	ZENER DIODE 12V	1/2W /-5%	
ZD902	996500040221	ZENER DIODE 5V1	1/2W /-5%	
ZD903	996510004909	ZENER DIODE 18V	1/2W	
ZD904	996510022199	ZENER DIODE 36V	1/2W (TAPE TYP	
ZD905	996500040221	ZENER DIODE 5V1	1/2W /-5%	
ZD906	996500040575	ZENER DIODE 12V	1/2W /-5%	
ZD907	996500040225	ZENER DIODE 9V1	1/2W /-5%	

LED BOARD

D511	996500040273	LED 3.1mm RED LONG LEAD	
PCB	996510028179	MO P.C BOARD	28.00X35.00mm
SPOW	996510022201	TSVT H = 5mm	KPT-1105A 4 PINS

LOC.	Alt. 12Nc	Safety	Description
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POWER BOARD

L906	996510022186		CHOKE COIL 10UH+/-10%7.5MMX9.5
NTC901	996510016185	■	NTC THERMISTOR RESISTOR 5D2-10
PCB	996510028191		MP P.C.BOARD140.00X162.00mm R
Q901	996510028157		TRANSISTOR 2N5551 PNP TO-92 PA
Q902	996510028173		TRANSISTOR 2N5401 PNP TO-92 PA
Q903	996510028157		TRANSISTOR 2N5551 PNP TO-92 PA
Q904	996510028157		TRANSISTOR 2N5551 PNP TO-92 PA
Q905	996500040232		TRANSISTOR 2SC1815Y/2PC1815
Q906	996500040232		TRANSISTOR 2SC1815Y/2PC1815
Q907	996500040232		TRANSISTOR 2SC1815Y/2PC1815
R920	996510022203		METAL OXIDE FILM RESISTOR39K O
RV901	996510028228		VARISTOR 470V +/-10% FNR-10K47
T901	996510022226	■	SWITCHING TRANSFORMER BK-35-L0
T902	996510028187	■	SWITCHING TRANSFORMER BCK-60-L
TG901	996510028163		GAS DISCHAR GE TUBE DSP-301N-C
TG902	996510028163		GAS DISCHAR GE TUBE DSP-301N-C
ZD901	996500040575		ZENER DIODE 12V 1/2W /-5%
ZD902	996500040221		ZENER DIODE 5V1 1/2W /-5%
ZD903	996510004909		ZENER DIODE 18V 1/2W
ZD904	996510022199		ZENER DIODE 36V 1/2W (TAPE TYP)
ZD905	996500040221		ZENER DIODE 5V1 1/2W /-5%
ZD906	996500040575		ZENER DIODE 12V 1/2W /-5%
ZD907	996500040225		ZENER DIODE 9V1 1/2W /-5%

LED BOARD

D511	996500040273	LED 3.1mm RED LONG LEAD
PCB	996510028179	MO P.C.BOARD 28.00X35.00mm
SPOW	996510022201	TSVT.H = 5mm KPT-1105A 4 P NS

REVISION LIST

Version 1.0

*Initial release

=Alternative Codes

 =Safety Symbol